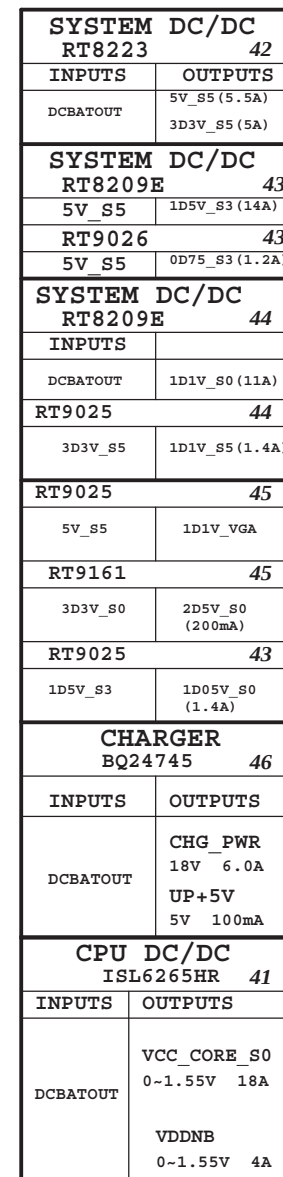


SJM50-DN Block Diagram

A cross-sectional diagram of a 5-layer printed circuit board (PCB). The layers are labeled from top to bottom: TOP, VCC, S, S, GND, and BOTTOM. The VCC layer is the thickest, followed by the two S (signal) layers, and then the TOP and BOTTOM layers. The GND layer is shown as a thin line between the two S layers.



緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

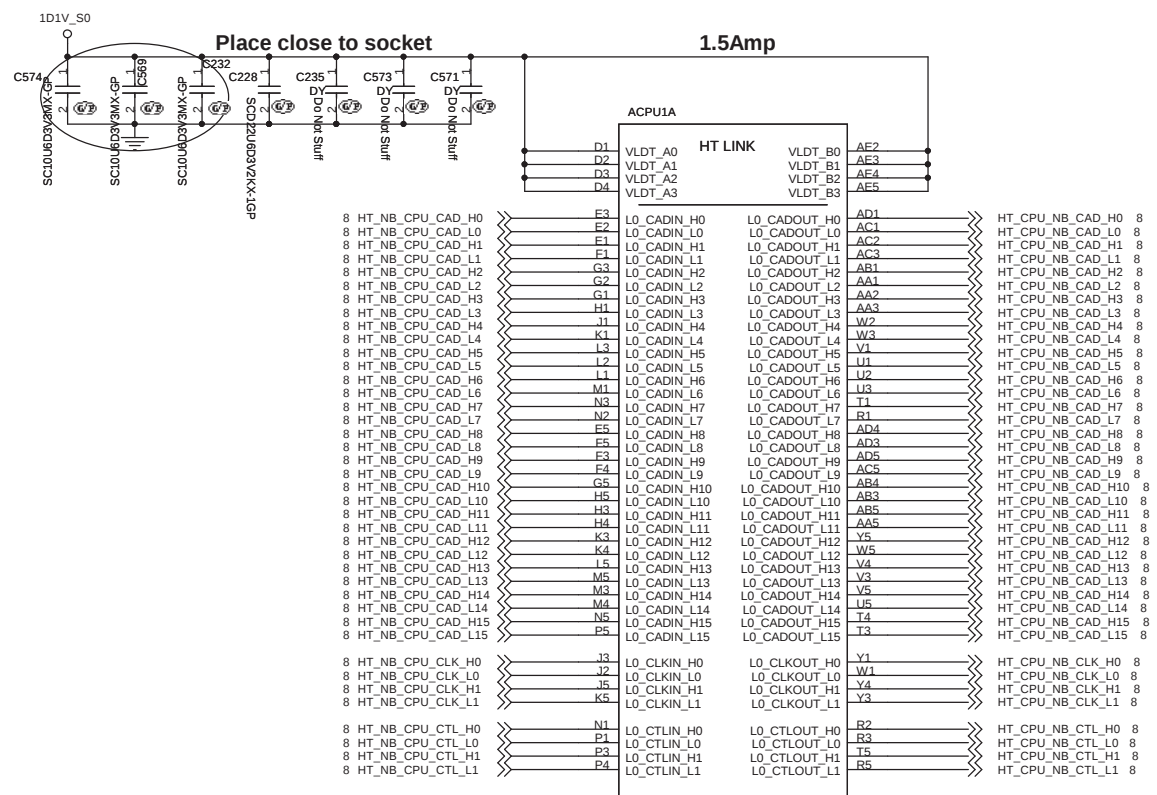
Title			
BLOCK DIAGRAM			
Size A3	Document Number SJM50-DN	Rev PD	
Date: Monday, April 26, 2010	Sheet 1	of 59	

<Core Design>

緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
History			
Size	Document Number		Rev
A3	SJM50-DN		PD
Date:	Monday, April 26, 2010		Sheet 2 of 59

<Core Design>

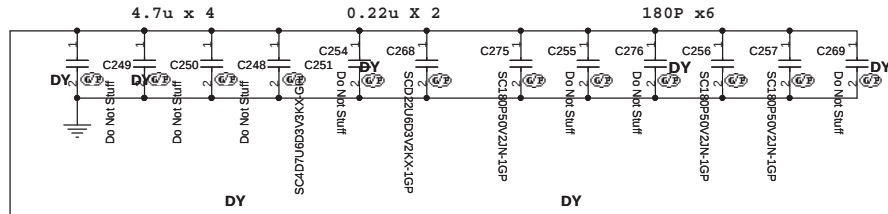
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
CLKGEN ICS9LPRS480			
Size	Document Number		Rev
A3	SJM50-DN		PD
Date:	Monday, April 26, 2010		Sheet 3 of 59



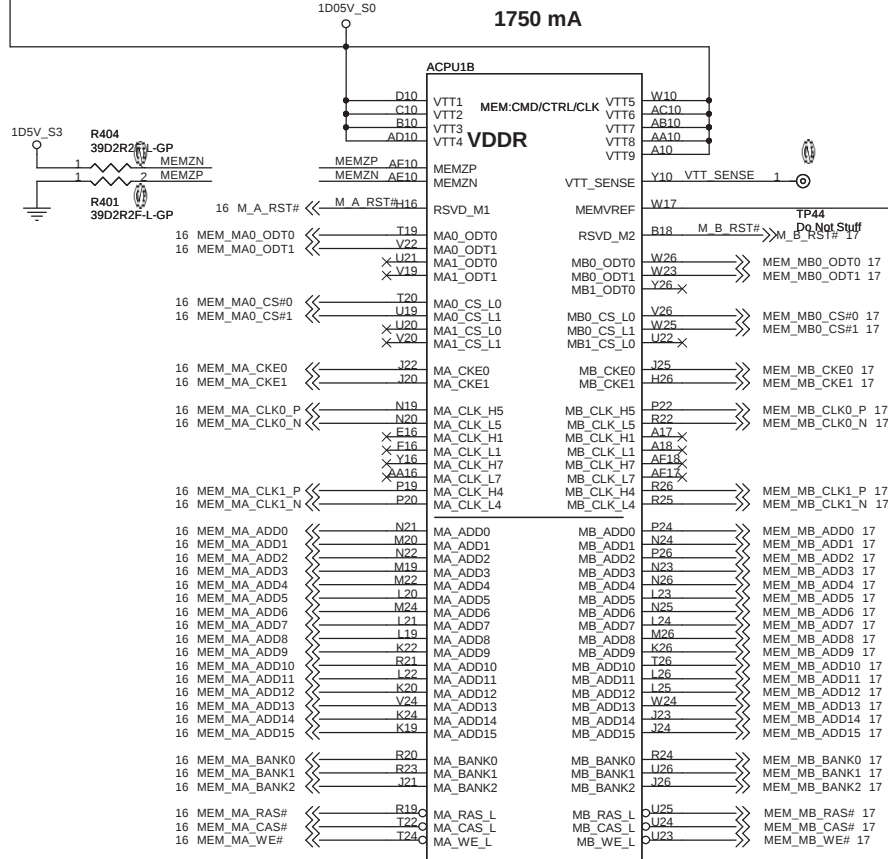
62.10055.111

SKT-BGA638H176

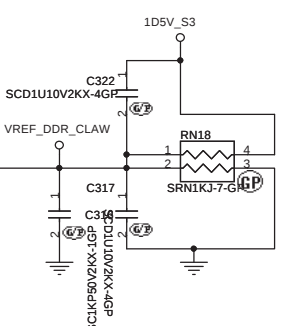
Place near to CPU



1750 mA



CLOSE TO CPU



ACPU1C	MEM/DATA	C11	MEM/DATA
MA_DATA0	MB_DATA0	C11	MEM_MB_DATA0 17
MA_DATA1	MB_DATA1	A11	MEM_MB_DATA1 17
MA_DATA2	MB_DATA2	A14	MEM_MB_DATA2 17
MA_DATA3	MB_DATA3	B14	MEM_MB_DATA3 17
MA_DATA4	MB_DATA4	G11	MEM_MB_DATA4 17
MA_DATA5	MB_DATA5	F11	MEM_MB_DATA5 17
MA_DATA6	MB_DATA6	D12	MEM_MB_DATA6 17
MA_DATA7	MB_DATA7	A13	MEM_MB_DATA7 17
MA_DATA8	MB_DATA8	A15	MEM_MB_DATA8 17
MA_DATA9	MB_DATA9	A16	MEM_MB_DATA9 17
MA_DATA10	MB_DATA10	A19	MEM_MB_DATA10 17
MA_DATA11	MB_DATA11	A20	MEM_MB_DATA11 17
MA_DATA12	MB_DATA12	C14	MEM_MB_DATA12 17
MA_DATA13	MB_DATA13	D14	MEM_MB_DATA13 17
MA_DATA14	MB_DATA14	C18	MEM_MB_DATA14 17
MA_DATA15	MB_DATA15	D18	MEM_MB_DATA15 17
MA_DATA16	MB_DATA16	D20	MEM_MB_DATA16 17
MA_DATA17	MB_DATA17	A21	MEM_MB_DATA17 17
MA_DATA18	MB_DATA18	D24	MEM_MB_DATA18 17
MA_DATA19	MB_DATA19	B20	MEM_MB_DATA19 17
MA_DATA20	MB_DATA20	C20	MEM_MB_DATA20 17
MA_DATA21	MB_DATA21	B22	MEM_MB_DATA21 17
MA_DATA22	MB_DATA22	C24	MEM_MB_DATA22 17
MA_DATA23	MB_DATA23	E23	MEM_MB_DATA23 17
MA_DATA24	MB_DATA24	F24	MEM_MB_DATA24 17
MA_DATA25	MB_DATA25	G25	MEM_MB_DATA25 17
MA_DATA26	MB_DATA26	G26	MEM_MB_DATA26 17
MA_DATA27	MB_DATA27	C26	MEM_MB_DATA27 17
MA_DATA28	MB_DATA28	C28	MEM_MB_DATA28 17
MA_DATA29	MB_DATA29	D26	MEM_MB_DATA29 17
MA_DATA30	MB_DATA30	G23	MEM_MB_DATA30 17
MA_DATA31	MB_DATA31	G24	MEM_MB_DATA31 17
MA_DATA32	MB_DATA32	A24	MEM_MB_DATA32 17
MA_DATA33	MB_DATA33	A23	MEM_MB_DATA33 17
MA_DATA34	MB_DATA34	AD24	MEM_MB_DATA34 17
MA_DATA35	MB_DATA35	AE24	MEM_MB_DATA35 17
MA_DATA36	MB_DATA36	AE26	MEM_MB_DATA36 17
MA_DATA37	MB_DATA37	AE25	MEM_MB_DATA37 17
MA_DATA38	MB_DATA38	AE25	MEM_MB_DATA38 17
MA_DATA39	MB_DATA39	AC22	MEM_MB_DATA39 17
MA_DATA40	MB_DATA40	AD22	MEM_MB_DATA40 17
MA_DATA41	MB_DATA41	AE20	MEM_MB_DATA41 17
MA_DATA42	MB_DATA42	AE20	MEM_MB_DATA42 17
MA_DATA43	MB_DATA43	AE24	MEM_MB_DATA43 17
MA_DATA44	MB_DATA44	AE23	MEM_MB_DATA44 17
MA_DATA45	MB_DATA45	AC20	MEM_MB_DATA45 17
MA_DATA46	MB_DATA46	AD20	MEM_MB_DATA46 17
MA_DATA47	MB_DATA47	AD18	MEM_MB_DATA47 17
MA_DATA48	MB_DATA48	AE18	MEM_MB_DATA48 17
MA_DATA49	MB_DATA49	AE18	MEM_MB_DATA49 17
MA_DATA50	MB_DATA50	AD14	MEM_MB_DATA50 17
MA_DATA51	MB_DATA51	AE19	MEM_MB_DATA51 17
MA_DATA52	MB_DATA52	AC18	MEM_MB_DATA52 17
MA_DATA53	MB_DATA53	AE16	MEM_MB_DATA53 17
MA_DATA54	MB_DATA54	AE15	MEM_MB_DATA54 17
MA_DATA55	MB_DATA55	AE13	MEM_MB_DATA55 17
MA_DATA56	MB_DATA56	AC12	MEM_MB_DATA56 17
MA_DATA57	MB_DATA57	AE11	MEM_MB_DATA57 17
MA_DATA58	MB_DATA58	Y11	MEM_MB_DATA58 17
MA_DATA59	MB_DATA59	AE14	MEM_MB_DATA59 17
MA_DATA60	MB_DATA60	AE14	MEM_MB_DATA60 17
MA_DATA61	MB_DATA61	AE11	MEM_MB_DATA61 17
MA_DATA62	MB_DATA62	AD11	MEM_MB_DATA62 17
MA_DATA63	MB_DATA63	AD11	MEM_MB_DATA63 17
MA_DM0	MB_DM0	A12	MEM_MB_DM0 17
MA_DM1	MB_DM1	B16	MEM_MB_DM1 17
MA_DM2	MB_DM2	A22	MEM_MB_DM2 17
MA_DM3	MB_DM3	E25	MEM_MB_DM3 17
MA_DM4	MB_DM4	AE26	MEM_MB_DM4 17
MA_DM5	MB_DM5	AE22	MEM_MB_DM5 17
MA_DM6	MB_DM6	AC16	MEM_MB_DM6 17
MA_DM7	MB_DM7	AD12	MEM_MB_DM7 17
MA_DQS_H0	MB_DQS_H0	C12	MEM_MB_DQS0_P 17
MA_DQS_L0	MB_DQS_L0	B12	MEM_MB_DQS0_N 17
MA_DQS_H1	MB_DQS_H1	D16	MEM_MB_DQS1_P 17
MA_DQS_L1	MB_DQS_L1	C16	MEM_MB_DQS1_N 17
MA_DQS_H2	MB_DQS_H2	A24	MEM_MB_DQS2_P 17
MA_DQS_L2	MB_DQS_L2	A23	MEM_MB_DQS2_N 17
MA_DQS_H3	MB_DQS_H3	F26	MEM_MB_DQS3_P 17
MA_DQS_L3	MB_DQS_L3	E26	MEM_MB_DQS3_N 17
MA_DQS_H4	MB_DQS_H4	AC25	MEM_MB_DQS4_P 17
MA_DQS_L4	MB_DQS_L4	AC26	MEM_MB_DQS4_N 17
MA_DQS_H5	MB_DQS_H5	AE21	MEM_MB_DQS5_P 17
MA_DQS_L5	MB_DQS_L5	AE22	MEM_MB_DQS5_N 17
MA_DQS_H6	MB_DQS_H6	AE16	MEM_MB_DQS6_P 17
MA_DQS_L6	MB_DQS_L6	AD16	MEM_MB_DQS6_N 17
MA_DQS_H7	MB_DQS_H7	AE12	MEM_MB_DQS7_P 17
MA_DQS_L7	MB_DQS_L7	AE12	MEM_MB_DQS7_N 17

62.10055.111

<Core Design>

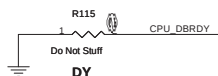
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

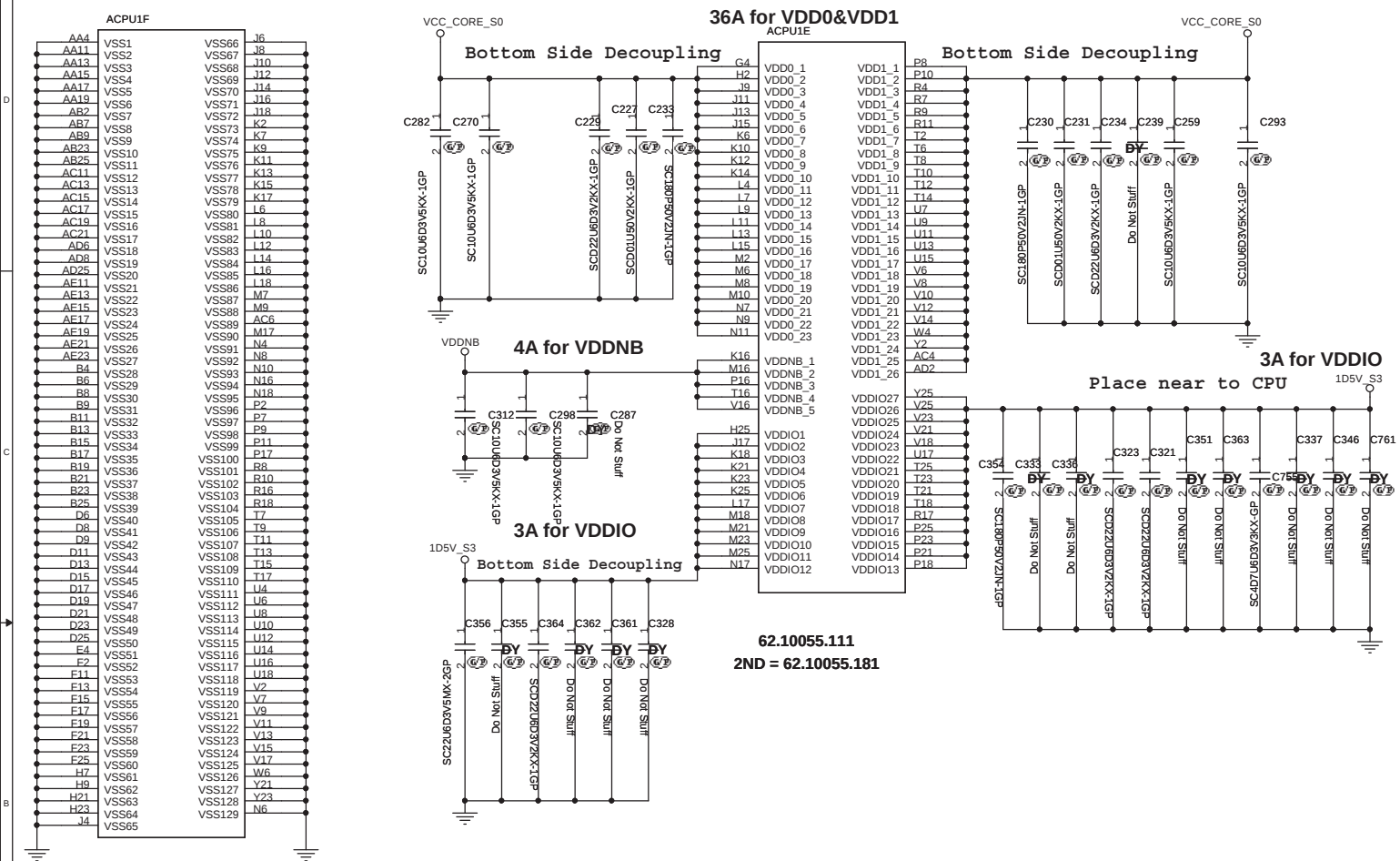
Title		
CPU DDR (2/4)		
Size	Document Number	Rev
A3	SJM50-DN	PD
Date:	Monday, April 26, 2010	Sheet 5 of 59

HDT Connectors

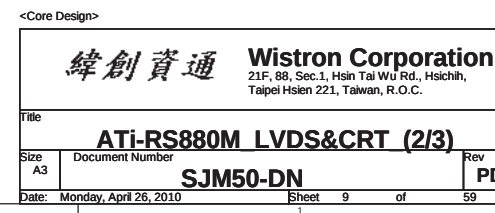


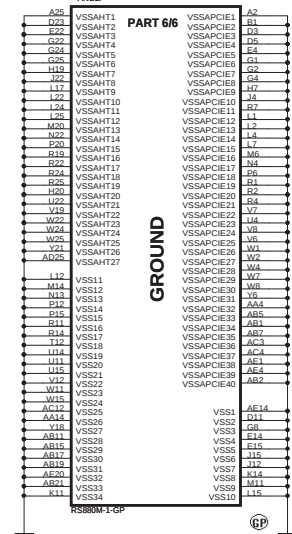
Title				CPU_Control&Debug_(3/4)			
Size		Document Number				Rev	
Custom		SJM50-DN				P1	
Date		Monday, April 26, 2010		Sheet		6 of 50	



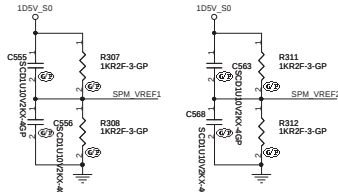



```
SUS_STAT#
Selects Loading of STRAPS From EEPROM
*1 : Bypass the loading of EEPROM straps and use Hardware Default Values
0 : I2C Master can load strap values from EEPROM if connected,
    or use default values if not connected
```



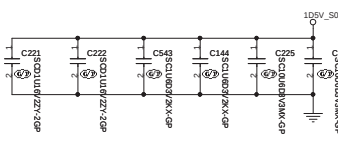


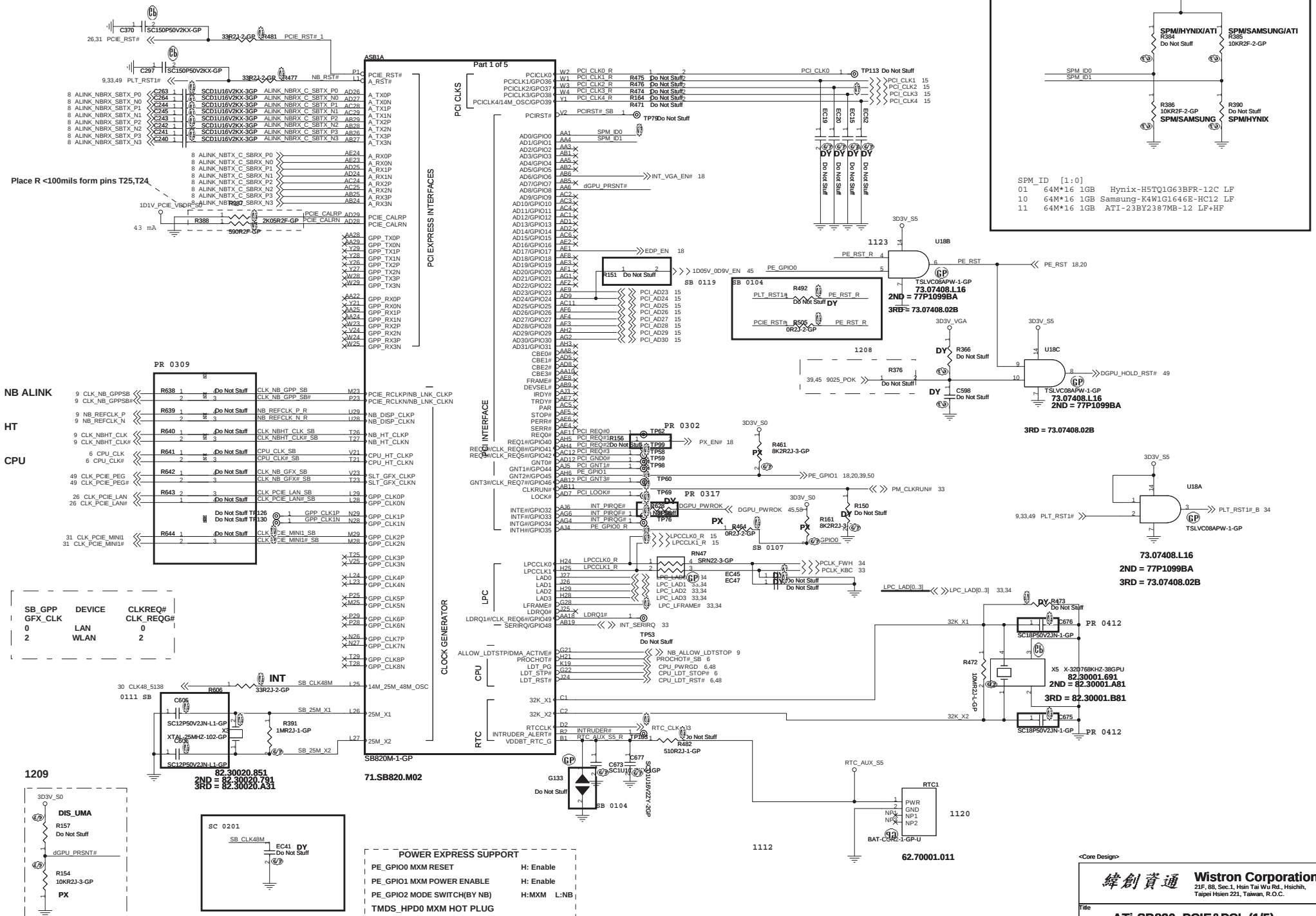
PAR 4 OF 6

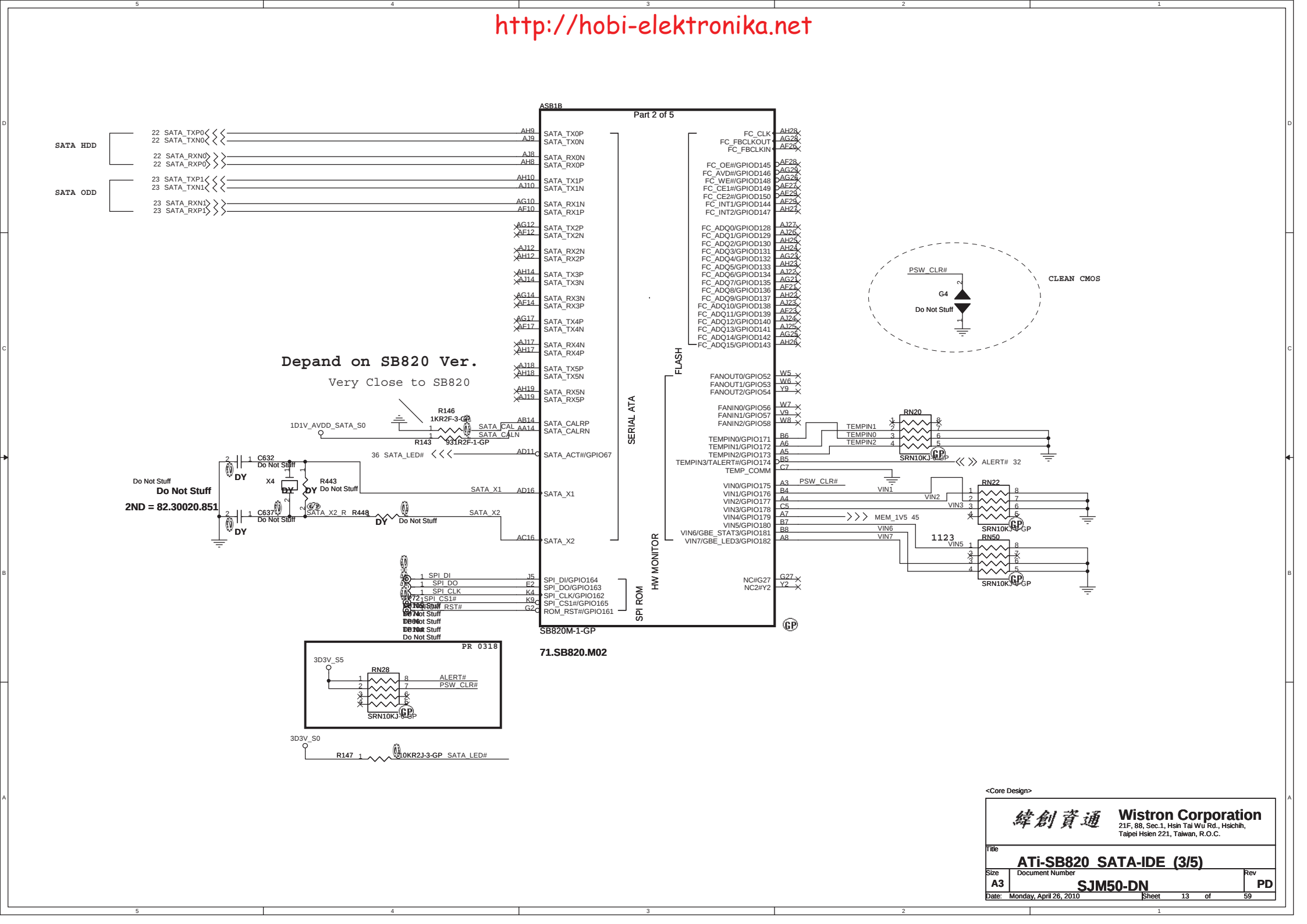


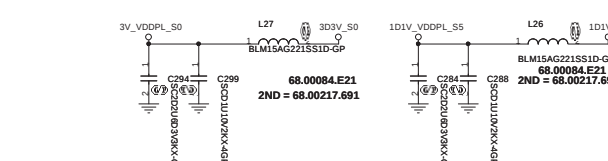
CLOSE TO SDRAM

CLOSE TO NB



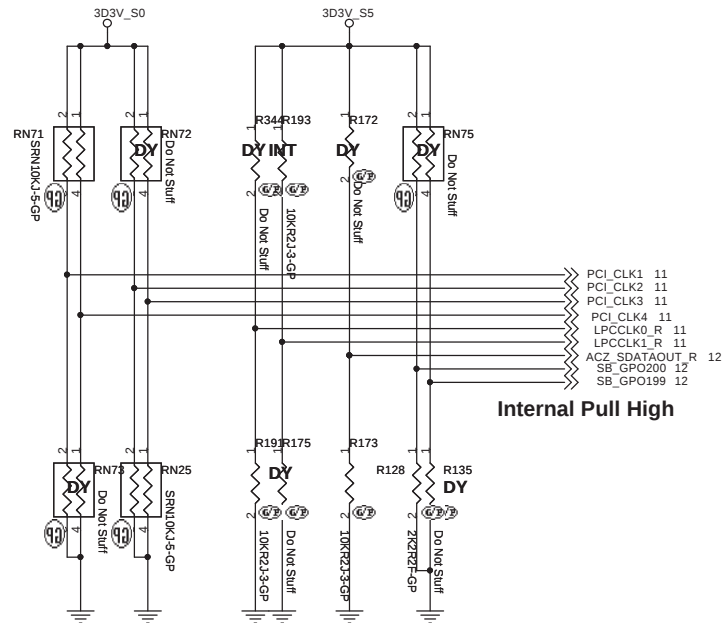






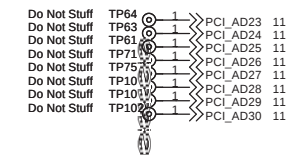
REQUIRED STRAPS

REQUIRED SYSTEM STRAPS



	PCI_CLK1	PCI_CLK2	PCI_CLK3	PCI_CLK4	LPC_CLK0	LPC_CLK1	AZ_SDOUT	GPIO200	GPIO199
PULL HIGH	ALLOW PCIE Gen2 DEFAULT	Watchdog Timer Enabled	USE DEBUG STRAP	non_Fusion CLOCK MODE DEFAULT	EC ENABLED	CLKGEN ENABLED DEFAULT	LOW POWER MODE	H,H = Reserved H,L = SPI ROM	
PULL LOW	FORCE PCIE Gen1	Watchdog Timer Disabled DEFAULT	IGNORE DEBUG STRAP DEFAULT	FUSION CLOCK MODE	EC DISABLED DEFAULT	CLKGEN DISABLED	PERFORMANCE MODE DEFAULT	L,H = LPC ROM (Default) L,L = FWH ROM	

DEBUG STRAPS



	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23
PULL HIGH	USE PCI PLL DEFAULT	DISABLE ILA AUTORUN DEFAULT	USE FC PLL DEFAULT	USE DEFAULT PCIE STRAPS DEFAULT	DISABLE PCI MEM BOOT DEFAULT
PULL LOW	BYPASS PCI PLL	ENABLE ILA AUTORUN	BYPASS FC PLL	USE EEPROM PCIE STRAPS	ENABLE PCI MEM BOOT

<Core Design>

緯創資通

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

ATI-SB820 STRAPPING (5/5)

Size

Document Number

A3

SJM50-DN

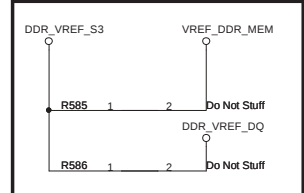
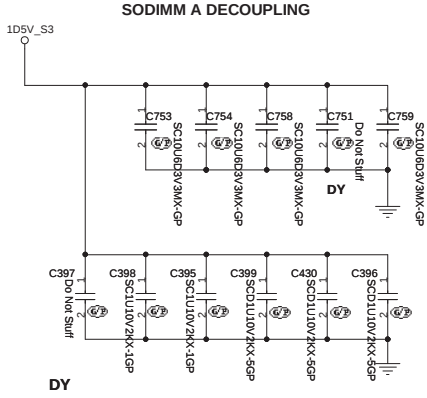
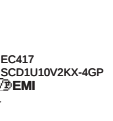
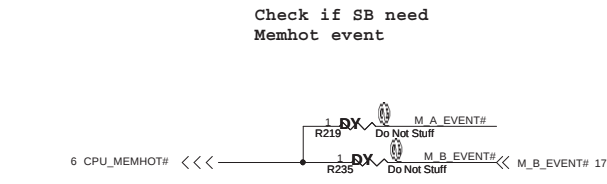
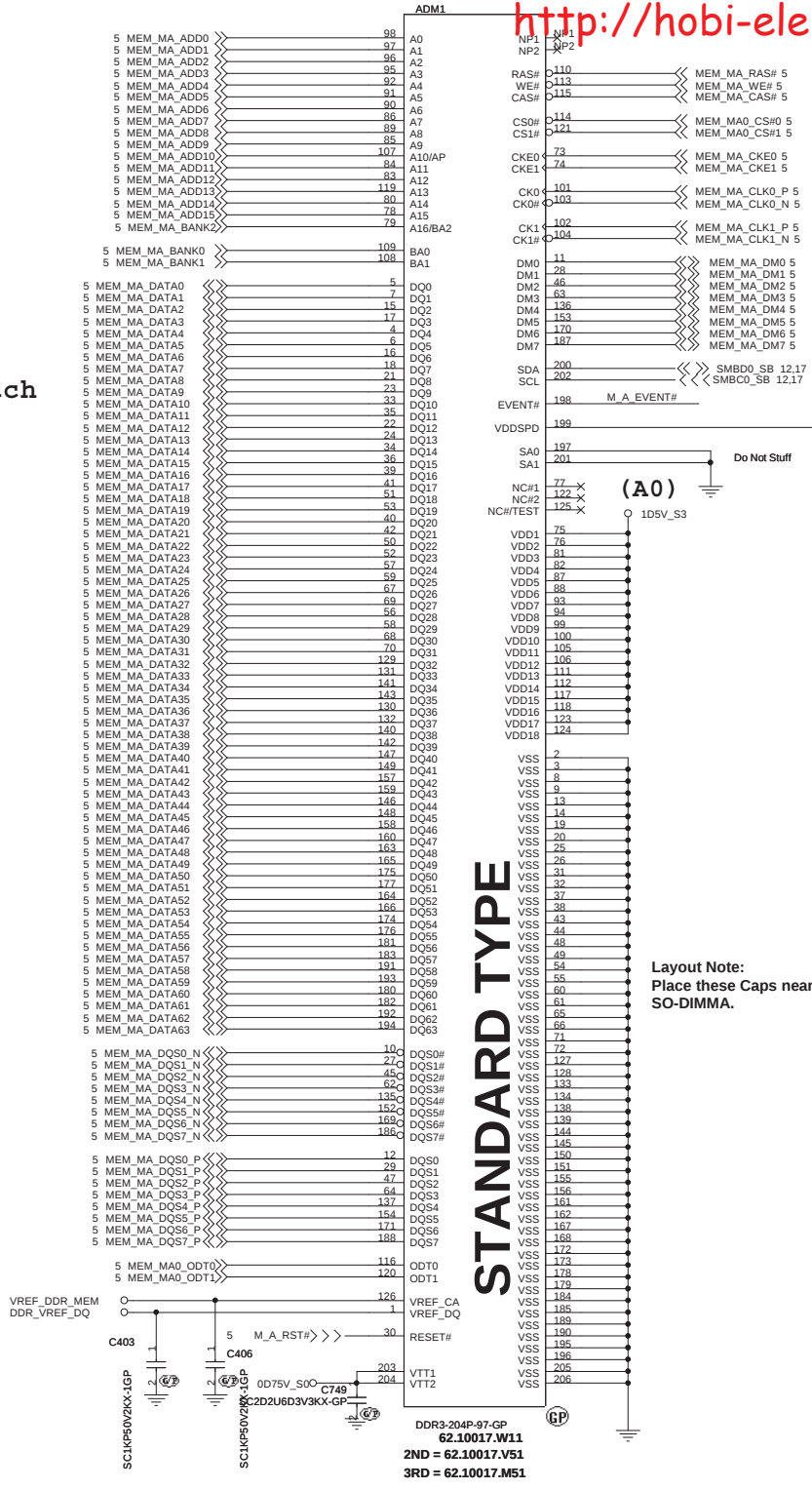
Rev

PD

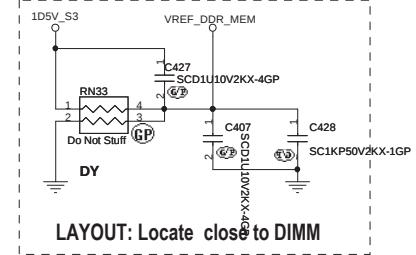
Date: Monday, April 26, 2010

Sheet 15 of 59

place ADM1
close to CPU
for length match

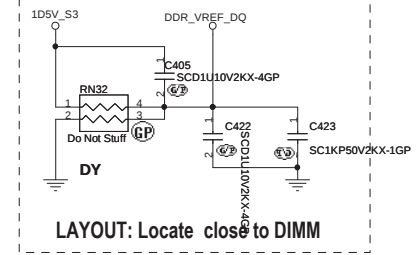


VREF_DDR_MEM

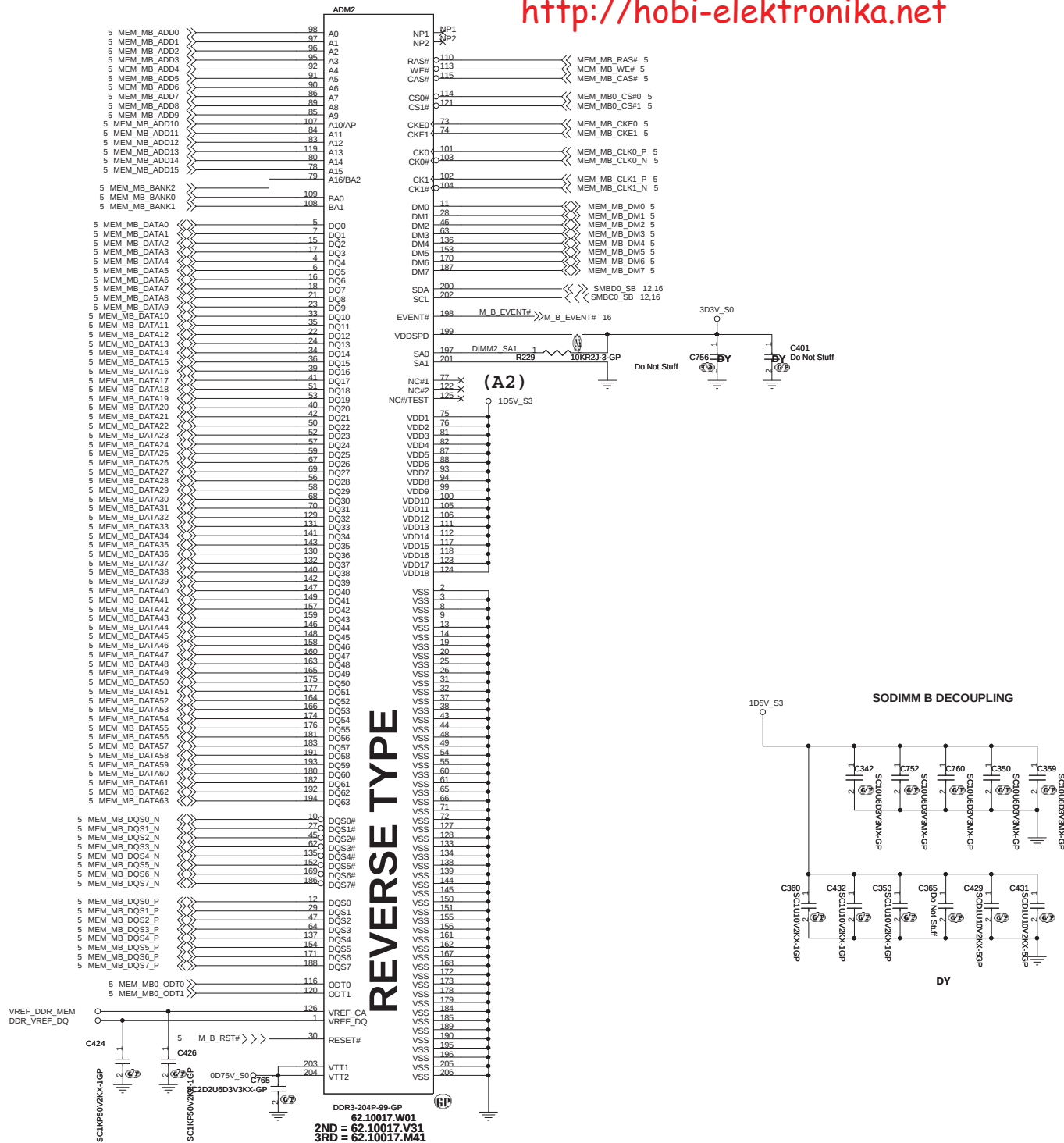


LAYOUT: Locate close to DIMM

DDR_VREF_DQ



LAYOUT: Locate close to DIMM



<Core Design>

緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Tainai Hsien 221, Taiwan, R.O.C.

Title				DDRIII SO-DIMM SKT 2			
Size	Document Number						Rev
Custom	SJM50-DN						PD
Date: Monday, April 26, 2010				Sheet 17 of 59			

Truth Table

Function	SEL
A_N to NB_1	L
A_N to NB_2	H

CRT

$\bar{E}$	S	YA	YB	YC	YD	Function
H	X	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Disable
L	L	IA0	IB0	IC0	ID0	S = 0
L	H	IA1	IB1	IC1	ID1	S = 1

EDID

Function Table

Input (S)	Function
L	B ₀ Connected to A
H	B ₁ Connected to A

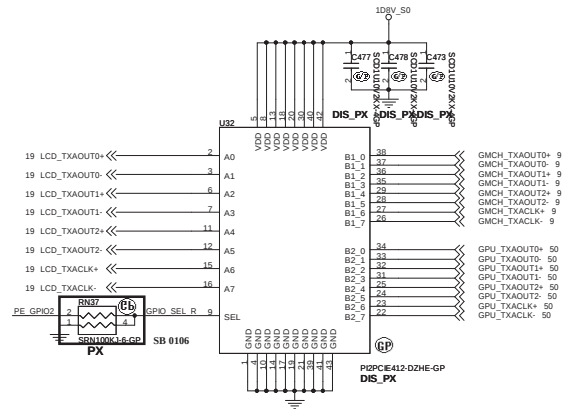
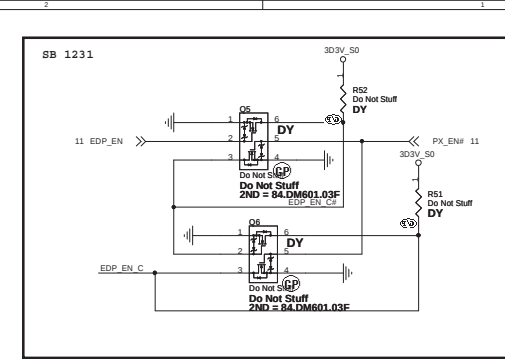
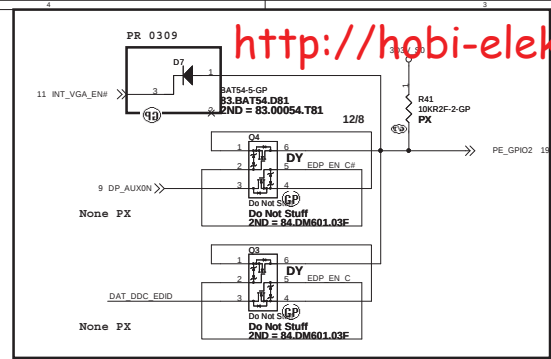
H = HIGH Logic Level L = LOW Logic Level

BLON_IN

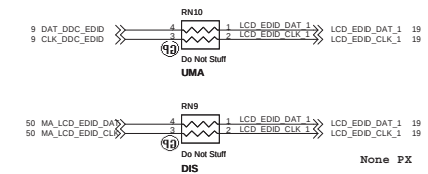
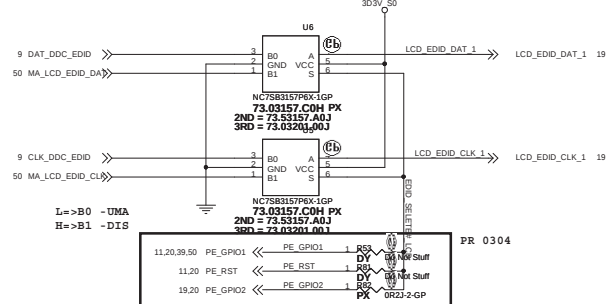
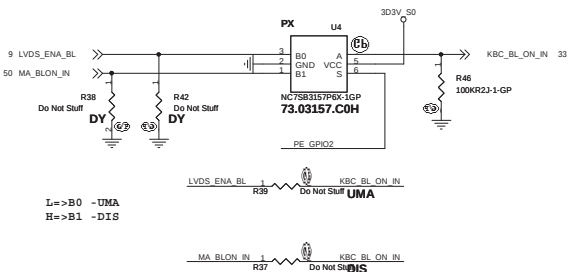
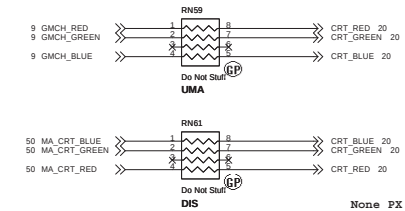
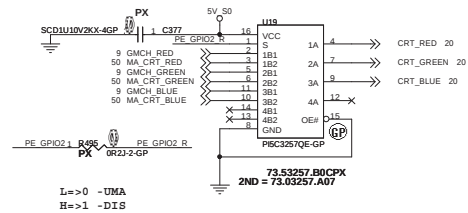
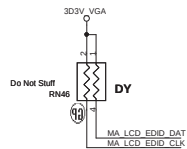
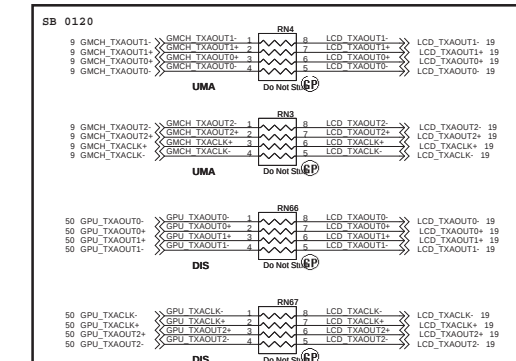
Function Table

Input (S)	Function
L	B ₀ Connected to A
H	B ₁ Connected to A

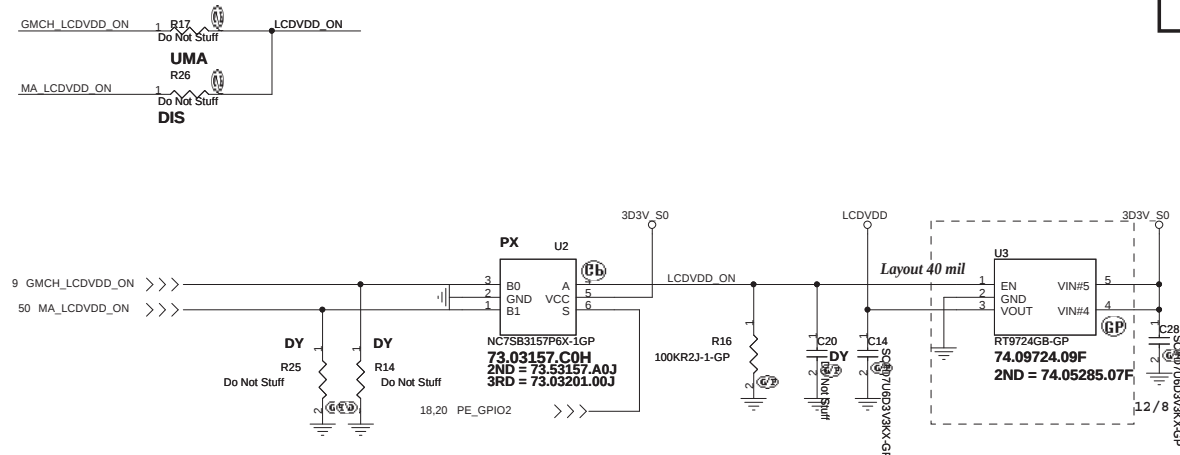
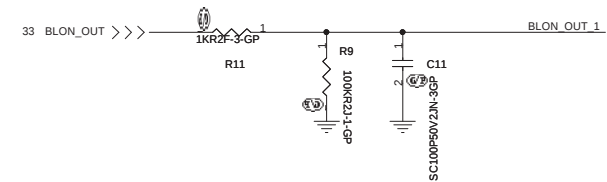
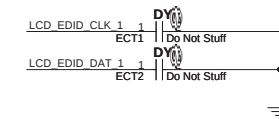
H = HIGH Logic Level L = LOW Logic Level

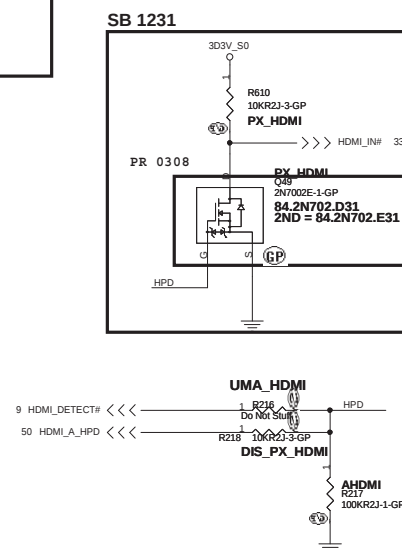
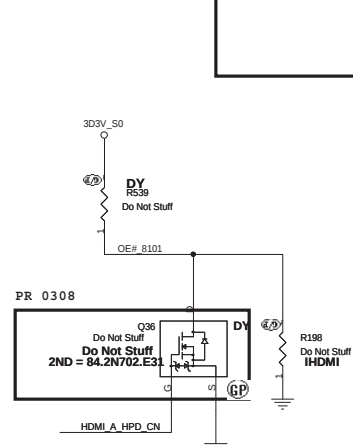
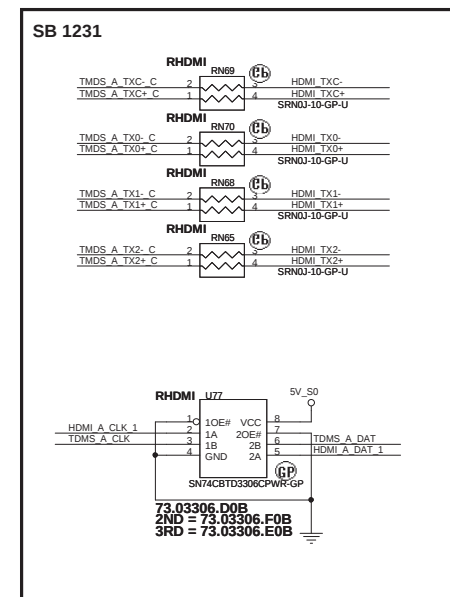
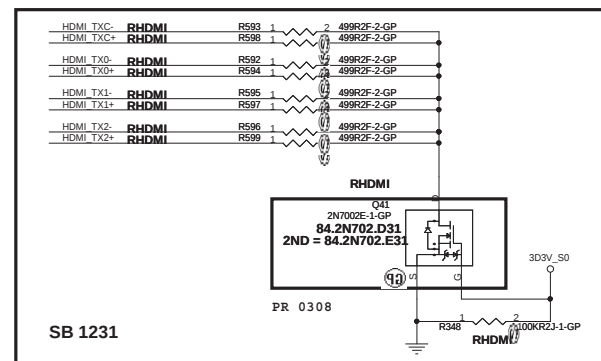
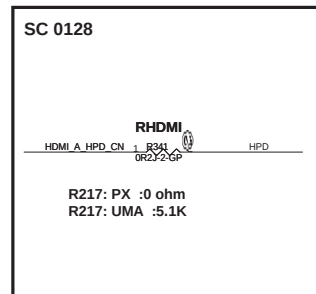
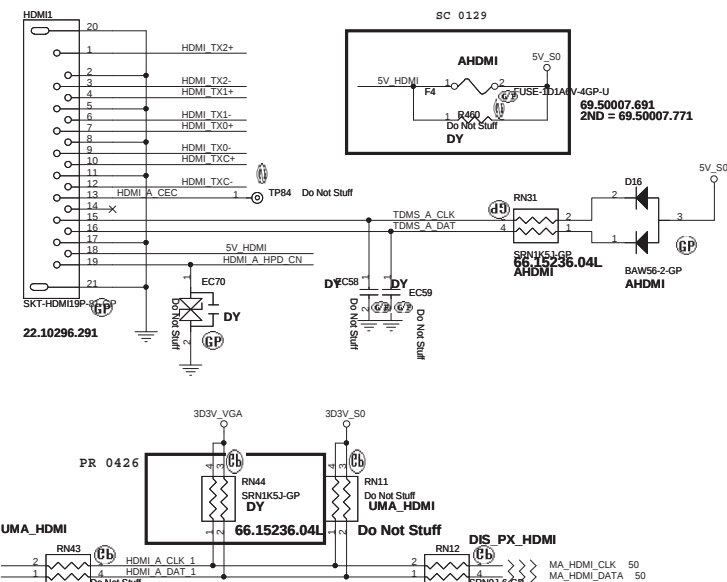
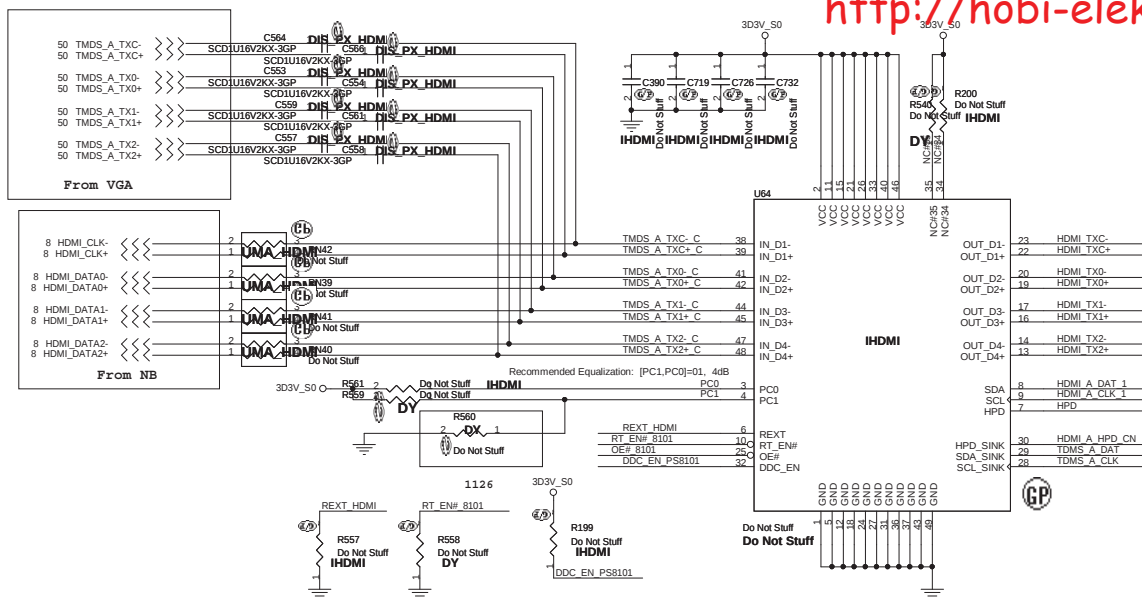


L=>A -UMA
H=>B -DIS



<http://hobi-elektronika.net>



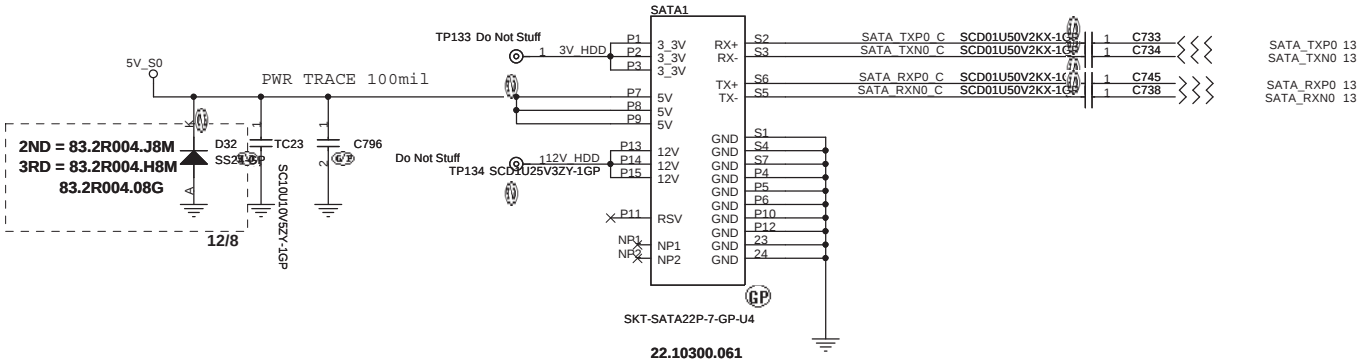


Recommended Equalization: [PC1,PC0]=00, 8dB
[PC1,PC0]=01, 4dB
[PC1,PC0]=10, 12dB
[PC1,PC0]=11, 0dB

```
OE#: internal pull down at ~30k ohm
HPD_SINK: internal pull down at ~80k ohm
RT_EN#: internal pull down at ~30k ohm
PC0,PC1: internal pull down at ~30k ohm
DDC_EN: internal pull down at ~30k ohm
```

SATA Connector

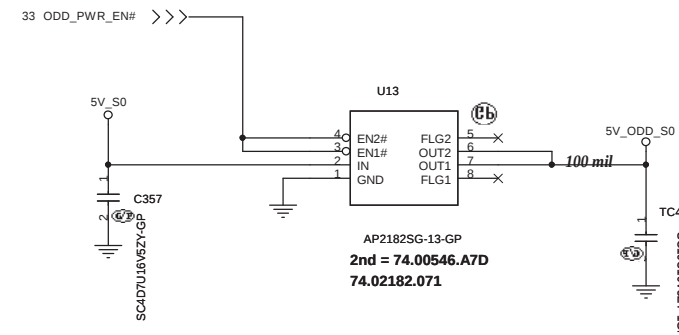
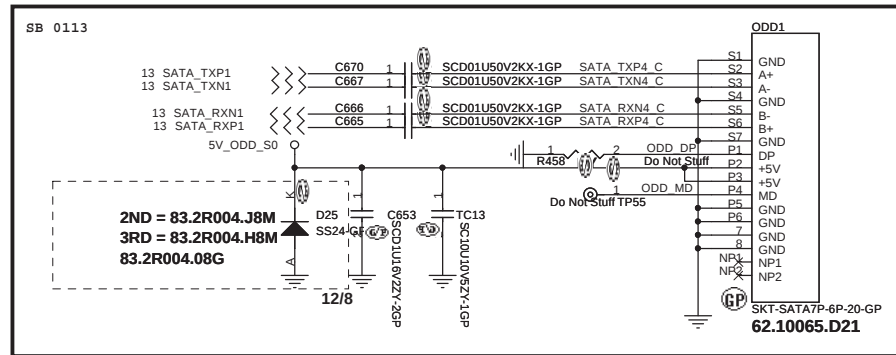
http://hobi-elektronika.net



<Core Design>

緯創資通		Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title			
HDD			
Size	Document Number	Rev	PD
SJM50-DN			
Date:	Monday, April 26, 2010	Sheet	22 of 59

ODD Connector



<Core Design>

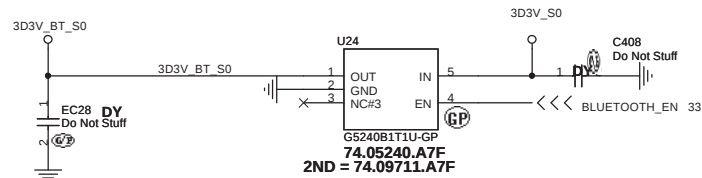
緯創資通

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

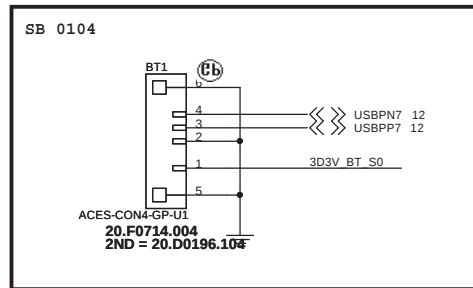
Title			ODD
Size	Document Number	Rev	PD
SJM50-DN			
Date: Monday, April 26, 2010	Sheet 23	of	59

BLUETOOTH MODULE

1.5A / High Active Voltage 2V



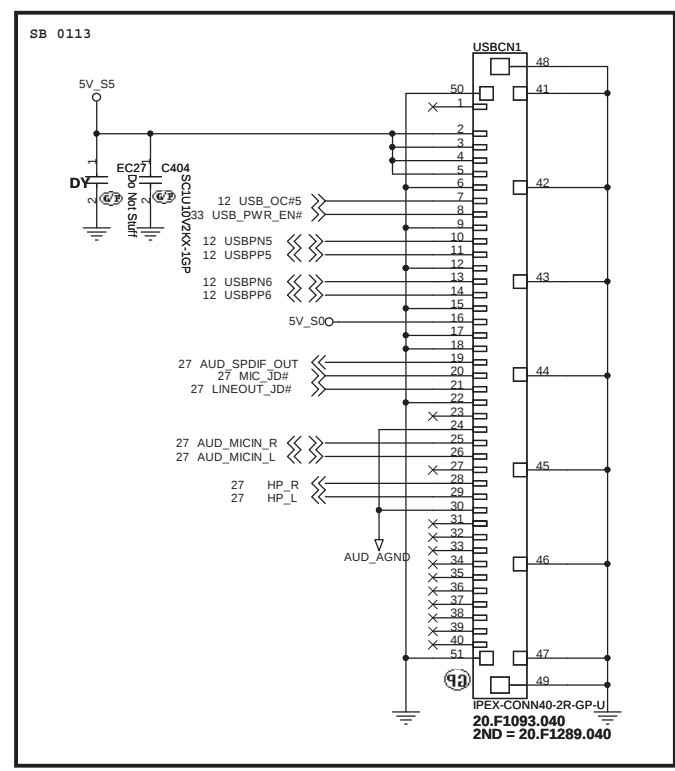
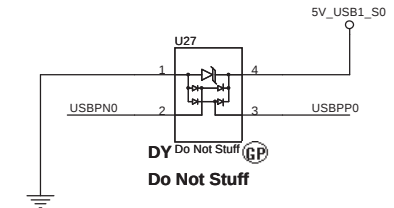
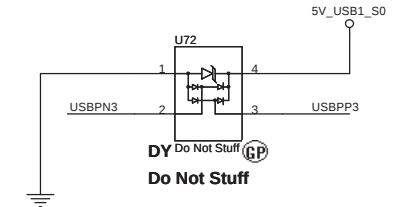
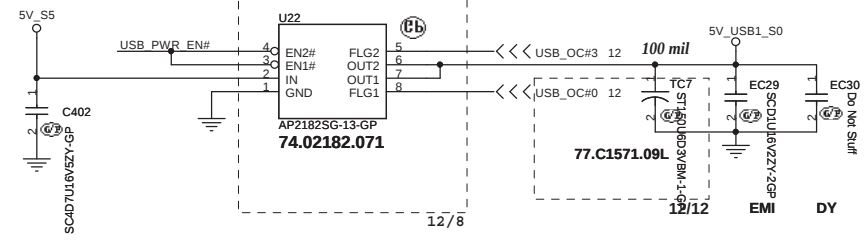
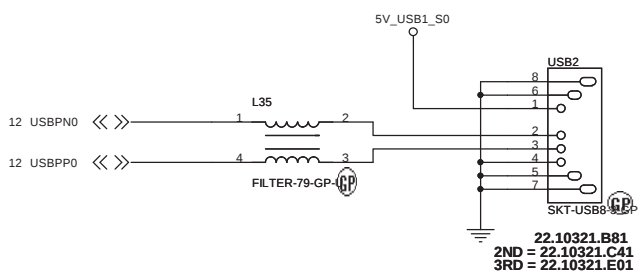
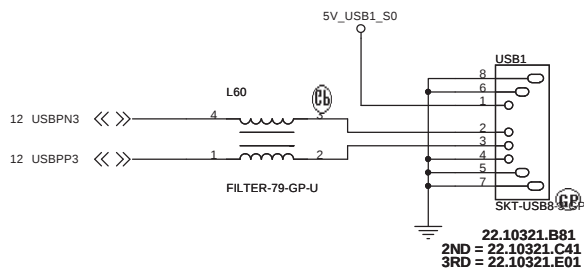
EC21 put near
BLUE1 / all
USB put one
choke near
connector by
EMI request

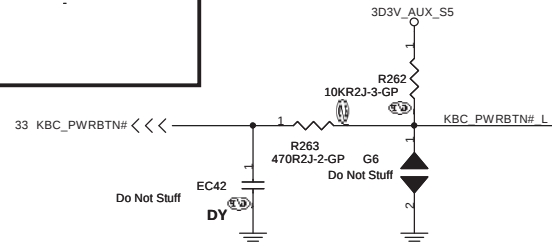
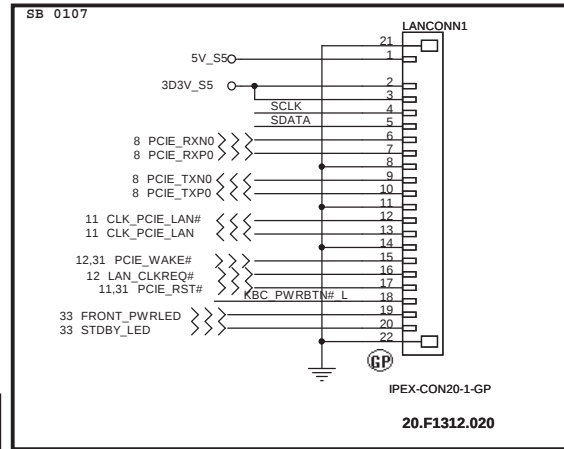
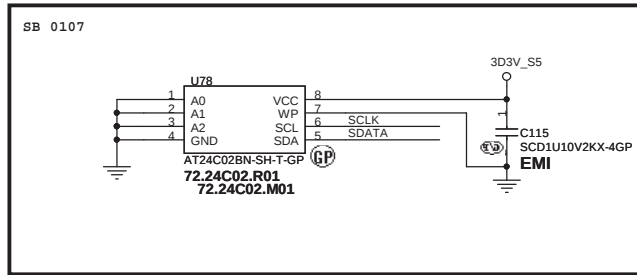
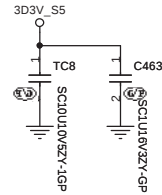


Pin 1 ->right side
20.D0197.104 Pin1 -> left side
change net sequence
can use JV50-CP Cable

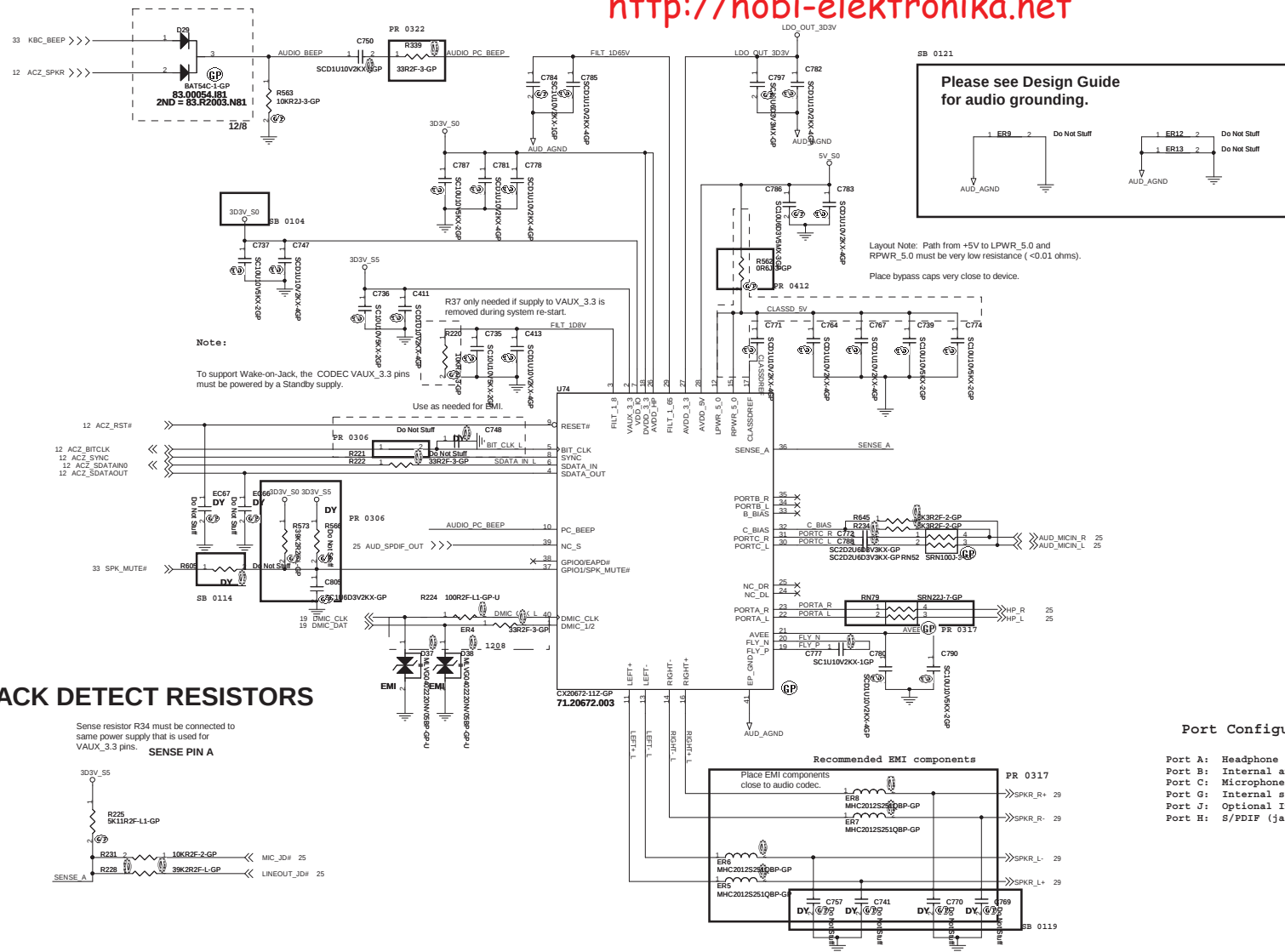
Eiger

緯創資通		Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
BLUETOOTH			
Size	Document Number	Rev	PD
	SJM50-DN		
Date:	Monday, April 26, 2010	Sheet	24 of 59





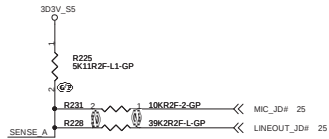
JV50



JACK DETECT RESISTORS

Sense resistor R34 must be connected to same power supply that is used for VAUX_3.3 pins. **SENSE PIN A**

SENSE PIN A



Port Configuration

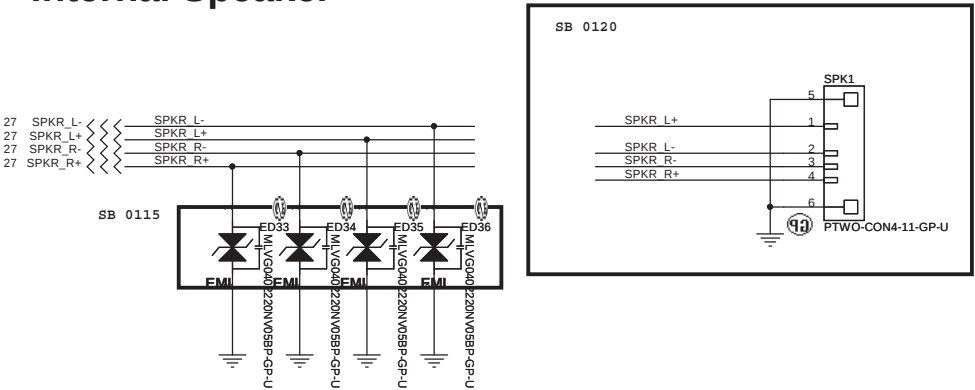
- Port A: Headphone jack (jack shared with S/PDIF)
Port B: Internal analog mono mic (stereo option)
Port C: Microphone jack
Port G: Internal stereo speakers
Port J: Optional Internal stereo digital mic
Port H: S/PDIF (jack shared with headphone)

AUDIO OP AMPLIFIER

Eiger

緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
AUDIO AMP			
Size	Document Number		Rev
	SJM50-DN		PD
Date:	Monday, April 26, 2010		Sheet 28 of 59

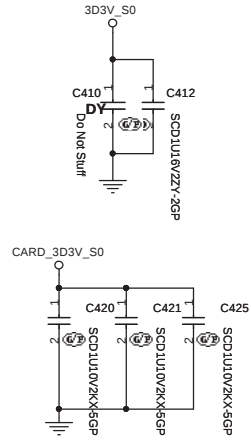
Internal Speaker



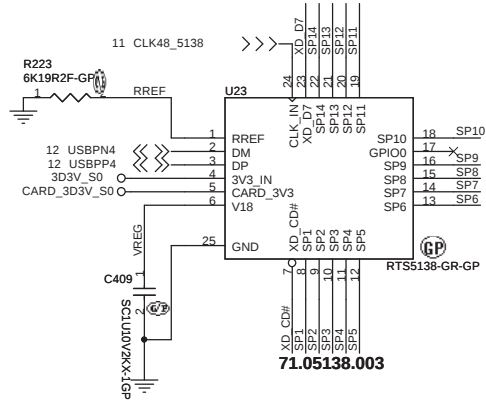
Eiger

5 IN1 CARD-READER

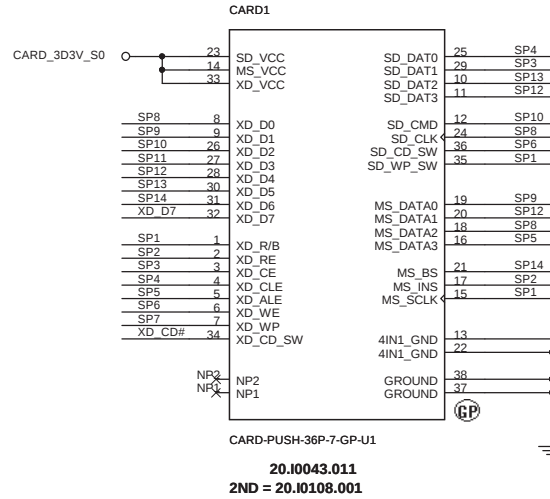
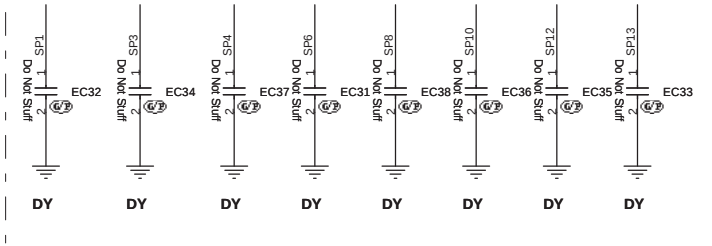
<http://hobi-elektronika.net>



C51,C52,C53 near CARD1 pin23, Pin14, Pin33



FOR EMI

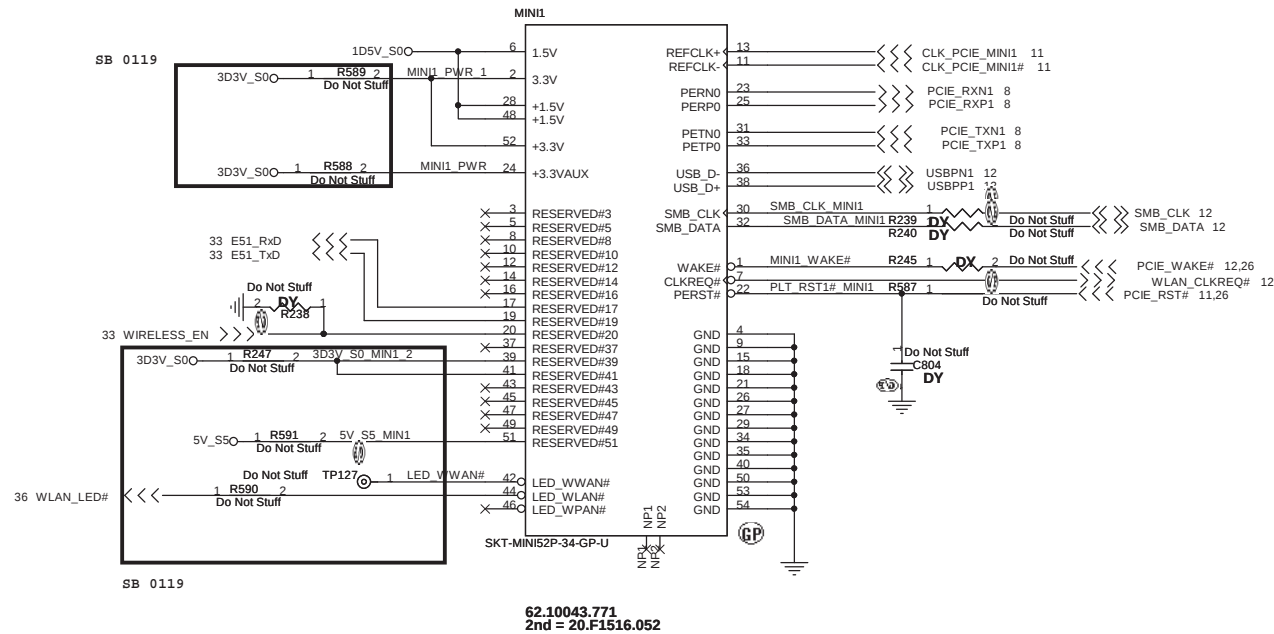


MORAR3

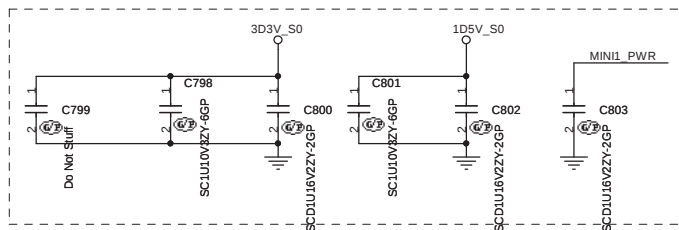
緯創資通 Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
CARDREADER	
Size	Document Number
SJM50-DN	
Date: Monday, April 26, 2010	Sheet 30 of 59
Rev PD	

Mini Card Connector(WLAN)

Support debug-card



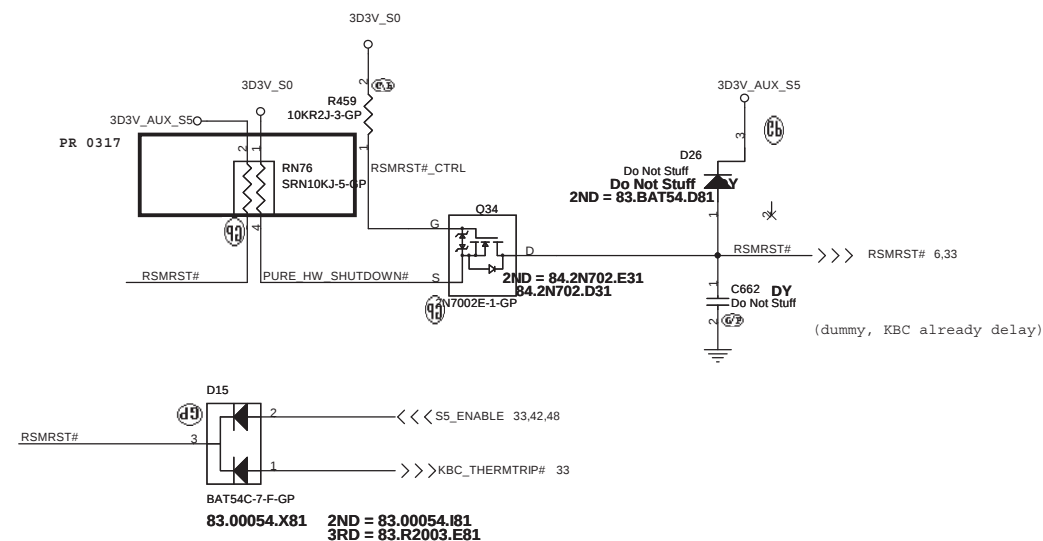
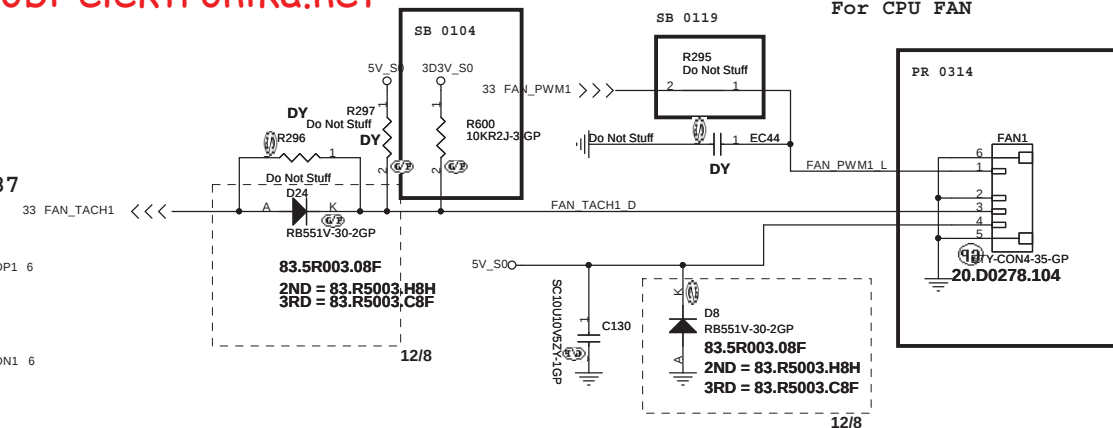
Place near MINI1



DY

Eiger

緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
MINI CARD	
Size	Document Number
	SJM50-DN
Date: Monday, April 26, 2010	Sheet 31 of 59
Rev	PD

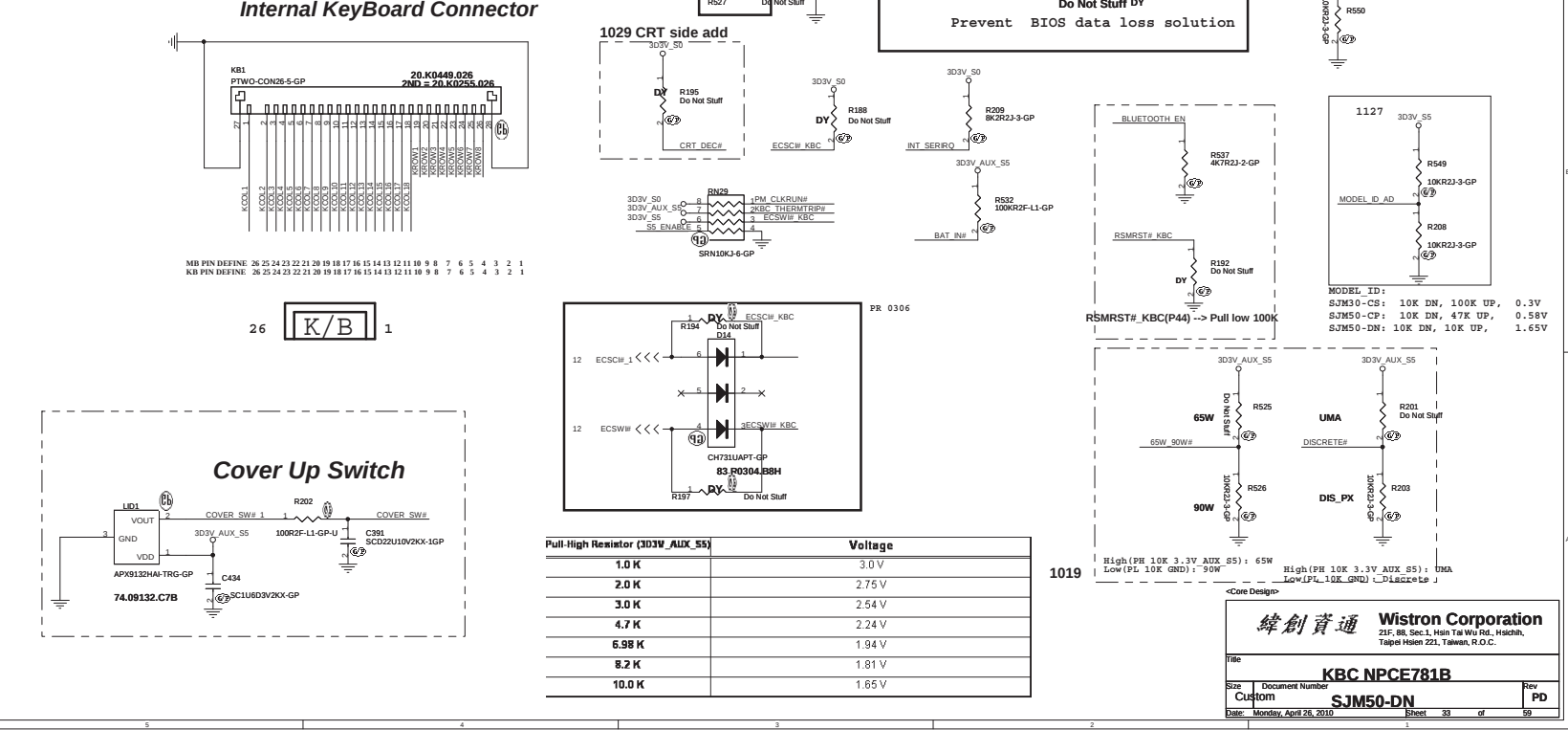
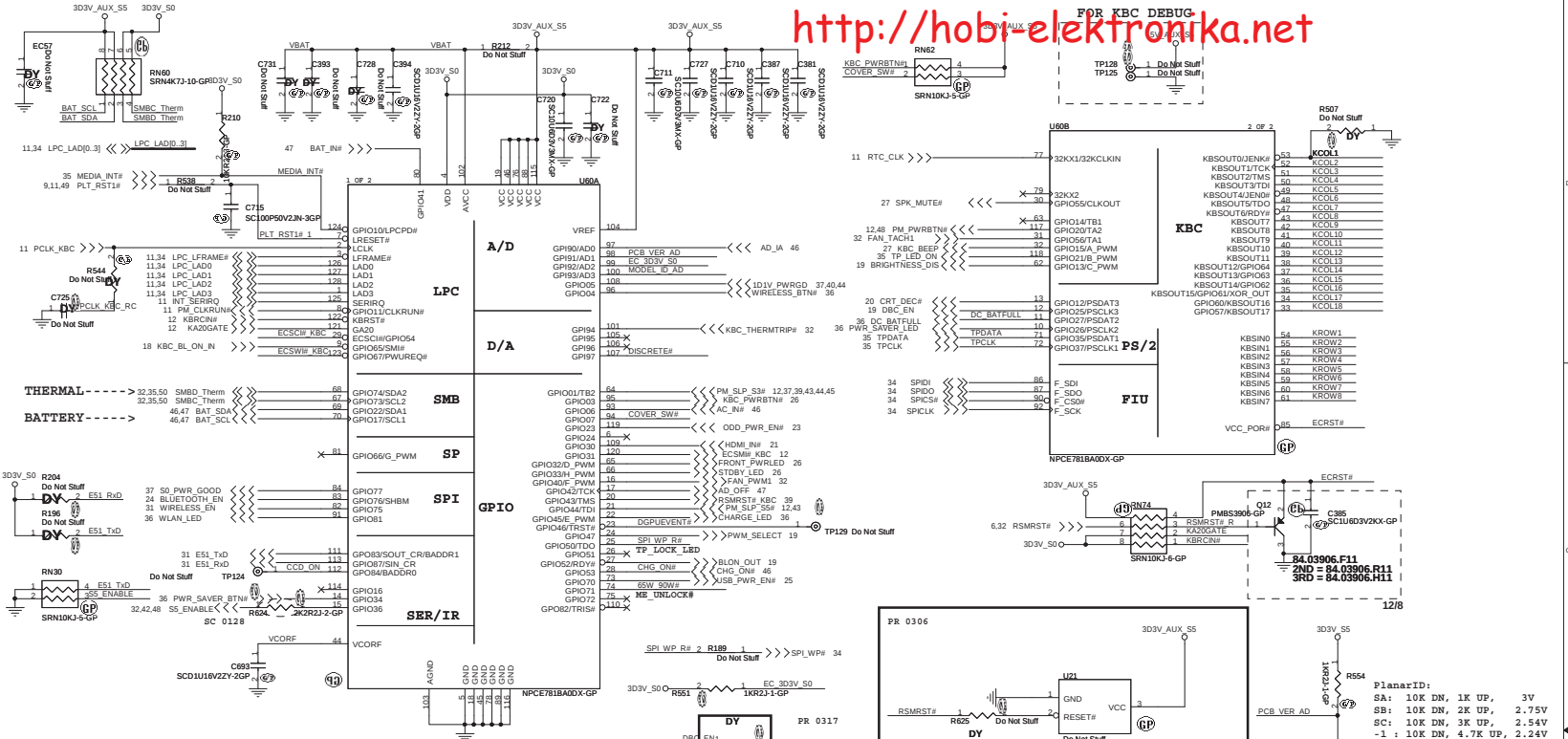


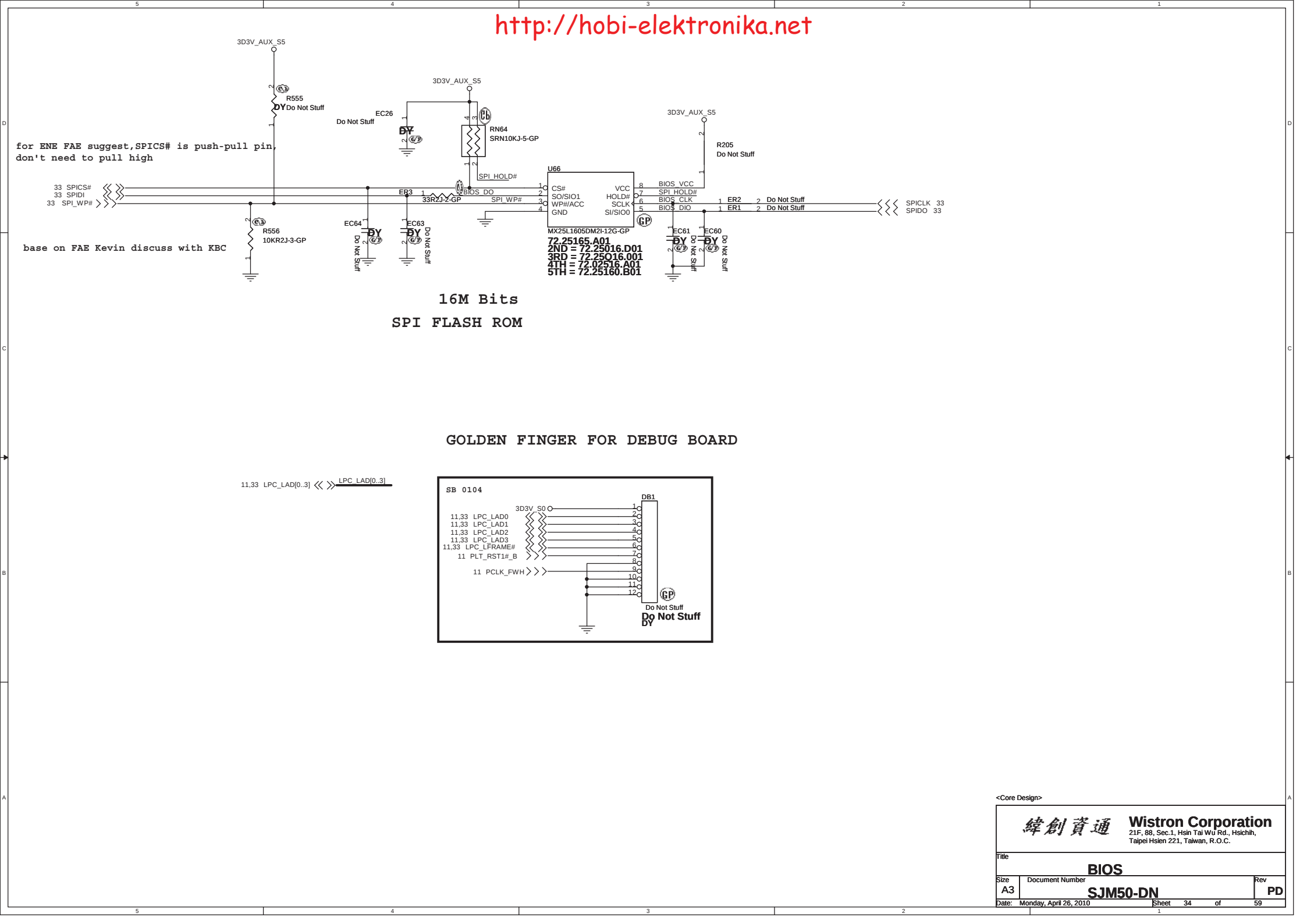
緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

G792

SJM50-DN

Sheet	32	of	59
-------	----	----	----



[illegible]

<http://hobi-elektronika.net>

for ENE FAE suggest, SPICS# is push-pull pin,
don't need to pull high

base on FAE Kevin discuss with KBC

16M Bits
SPI FLASH ROM

GOLDEN FINGER FOR DEBUG BOARD

SB 0104

11.33 LPC_LAD0
11.33 LPC_LAD1
11.33 LPC_LAD2
11.33 LPC_LAD3
11.33 LPC_LFRAME#
11 PLT_RST1#_B
11 PCLK_FWH >>

3D3V S0

DB1

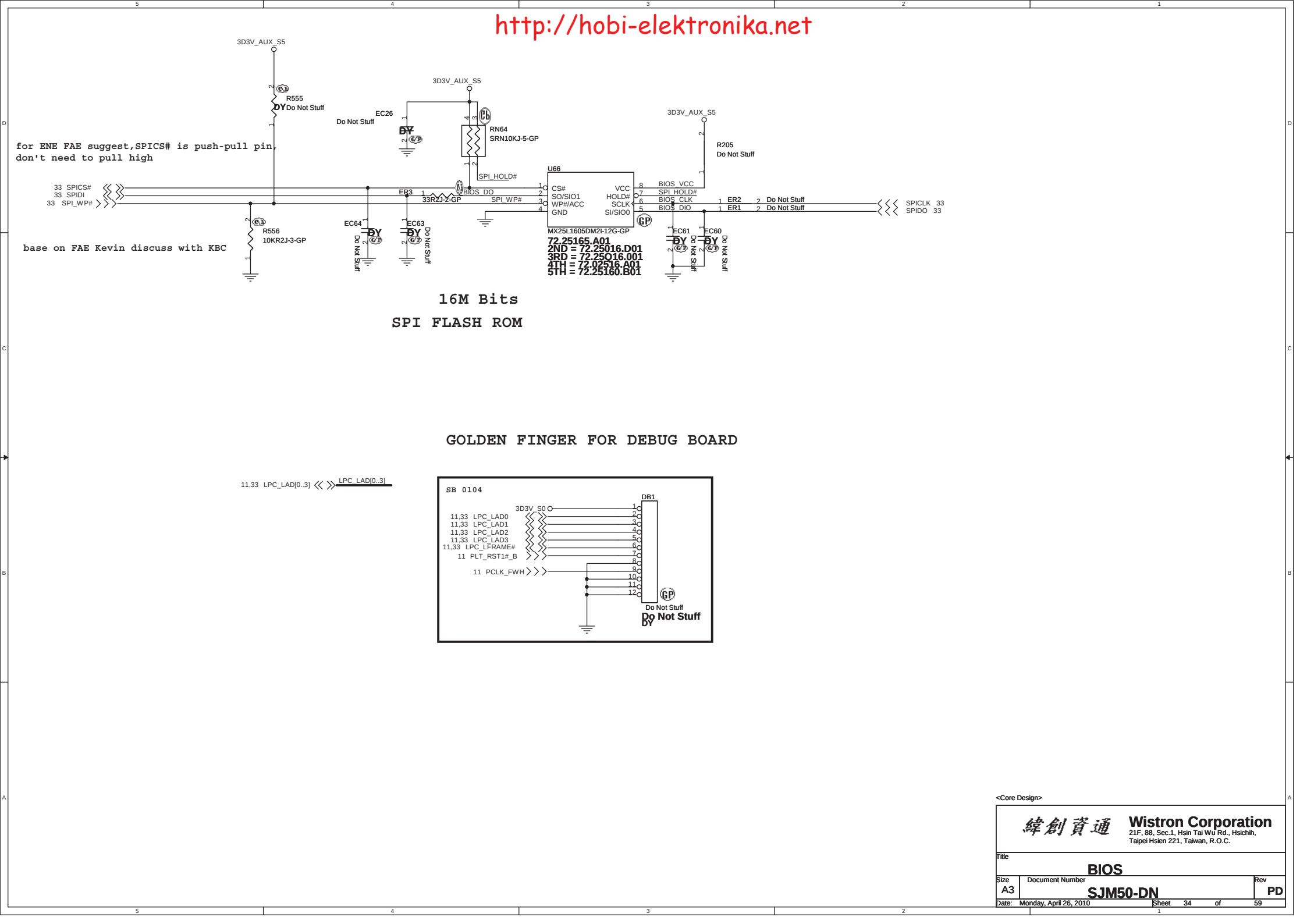
Do Not Stuff
DY

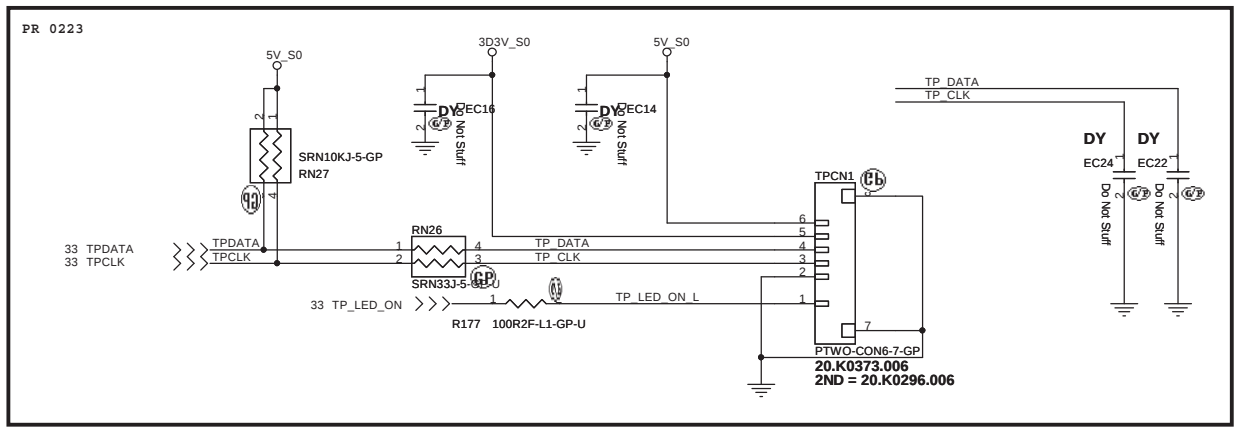
Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title
BIOS

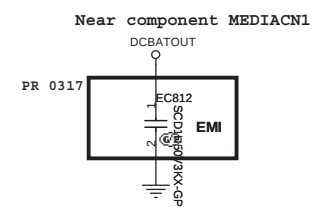
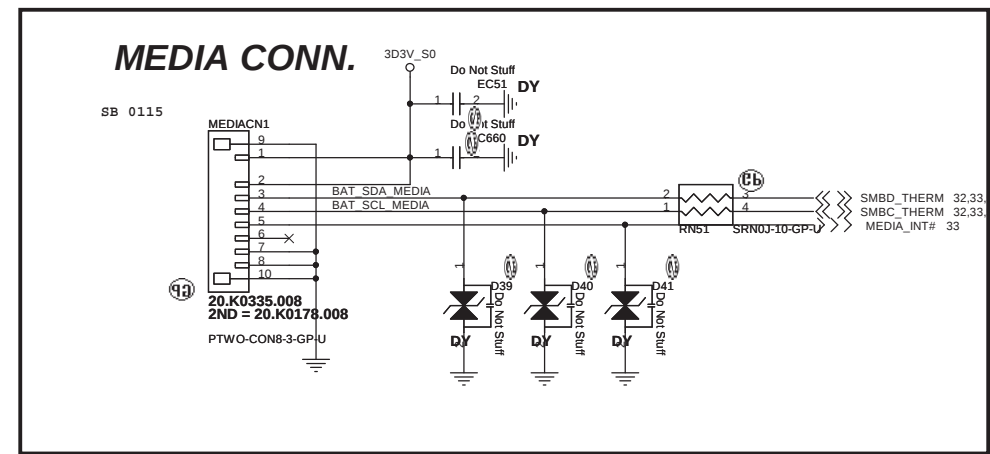
Size A3 Document Number **SJM50-DN** Rev PD

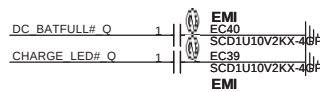
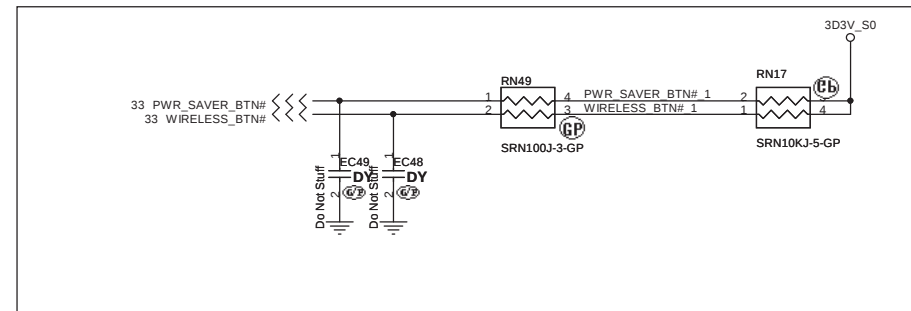
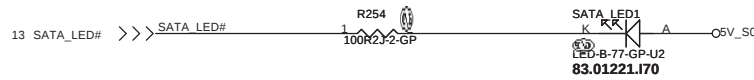
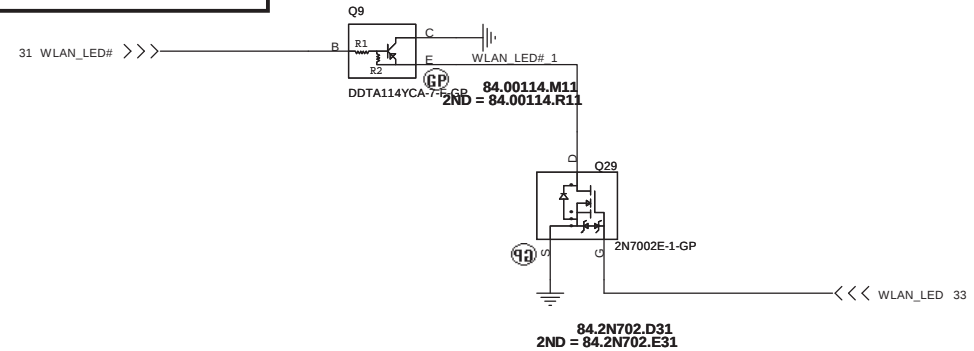
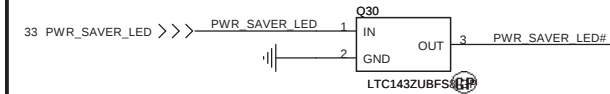
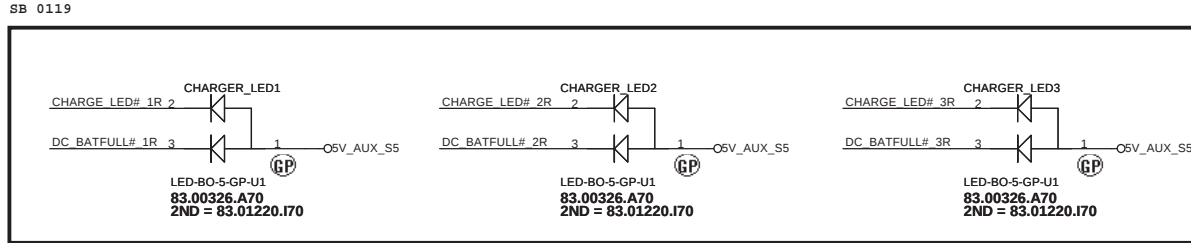
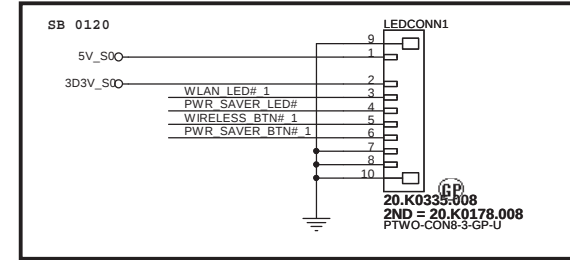
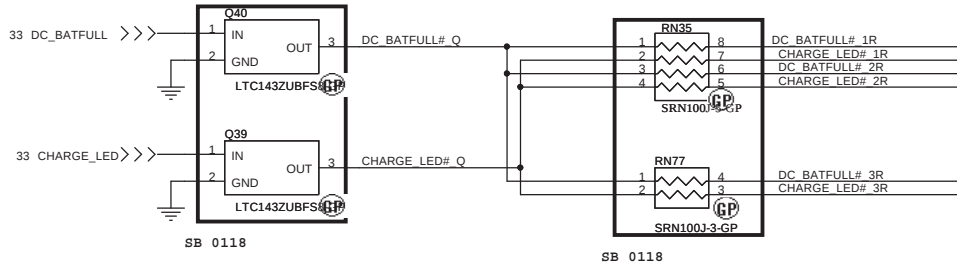
Date: Monday, April 26, 2010 Sheet 34 of 59

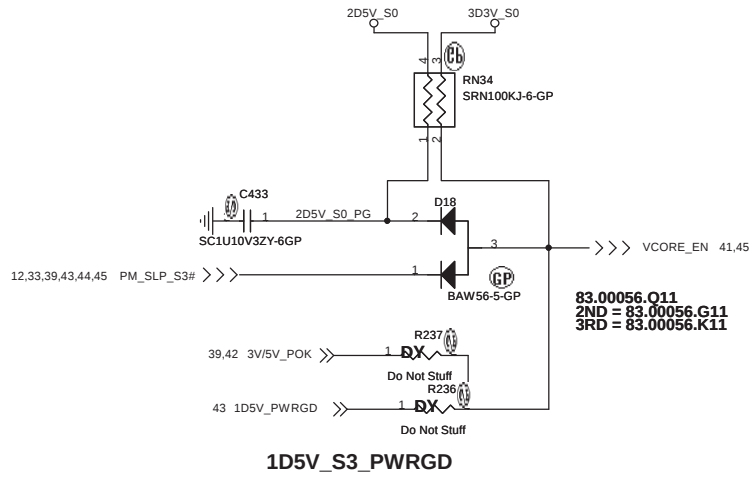




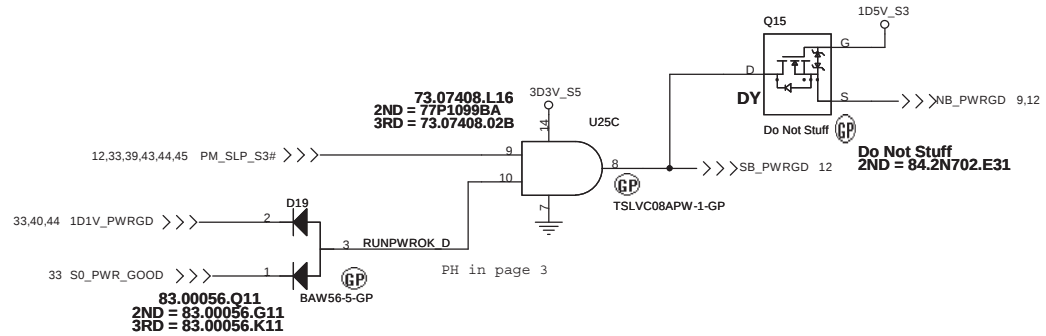
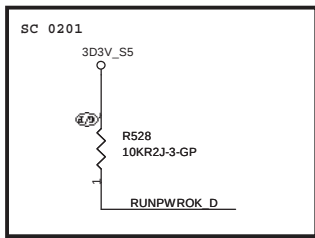
1 6
T/P



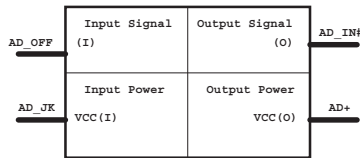




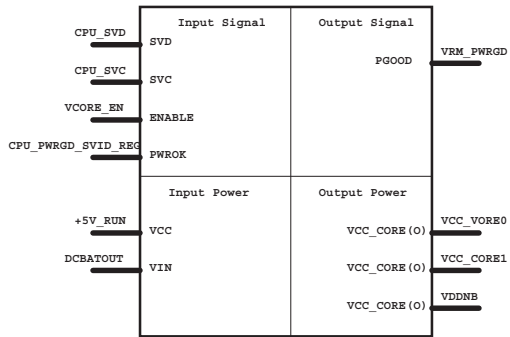
P/H @ 1D8V_S3 PAGE



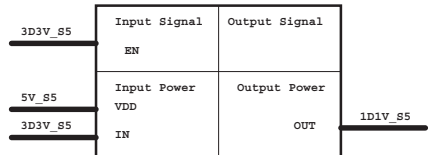
Adapter



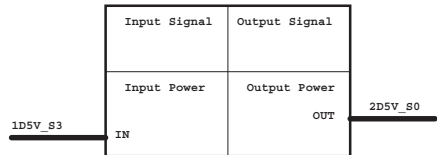
CPU_CORE ISL6265HRTZ



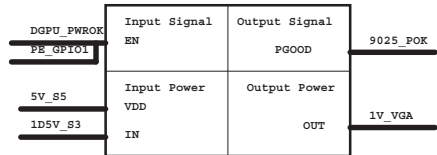
1D1V_S5 LDO RT9025



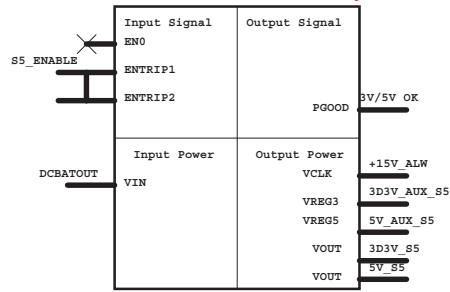
1V_VGA LDO R9025



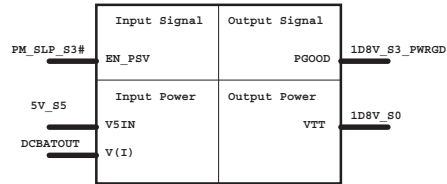
1V_VGA LDO RT9025



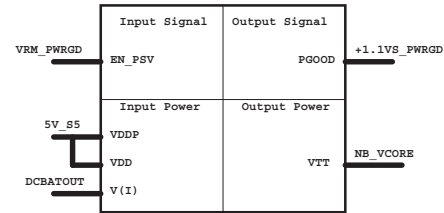
DCDC 5V/3D3V(RT8205A)



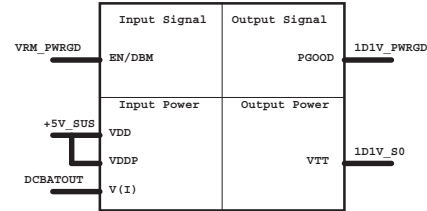
DCDC 1D8V(RT8051A)



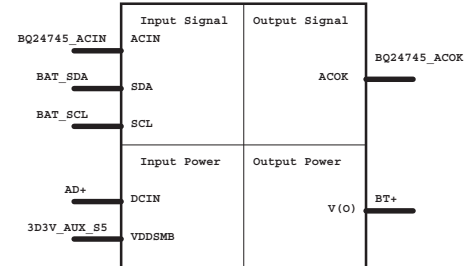
DCDC NB_VCORE (RT8208)



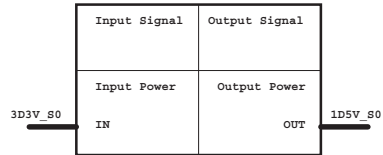
DCDC 1D1V(RT8209)



CHARGER BQ24745



1D5V LDO G9571

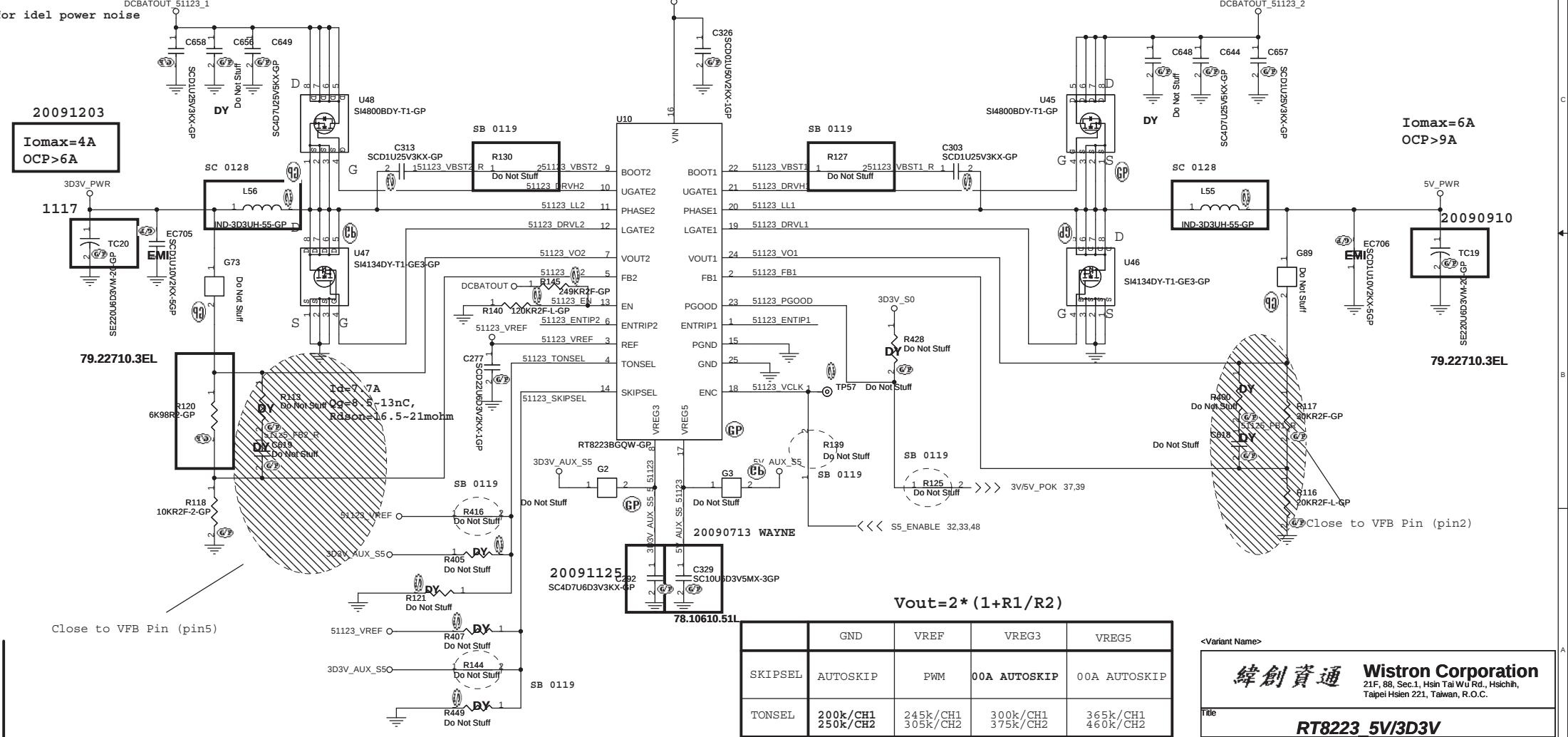
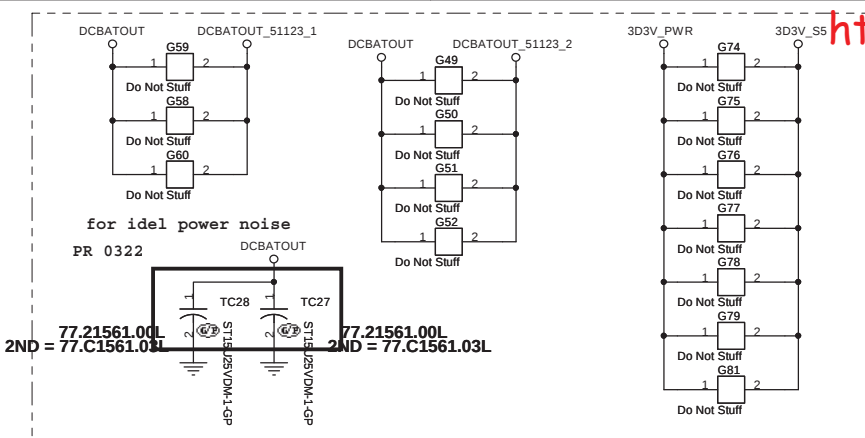
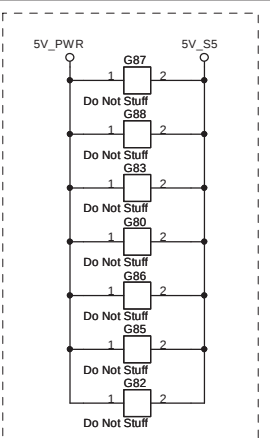
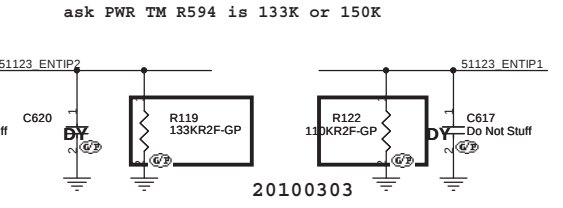
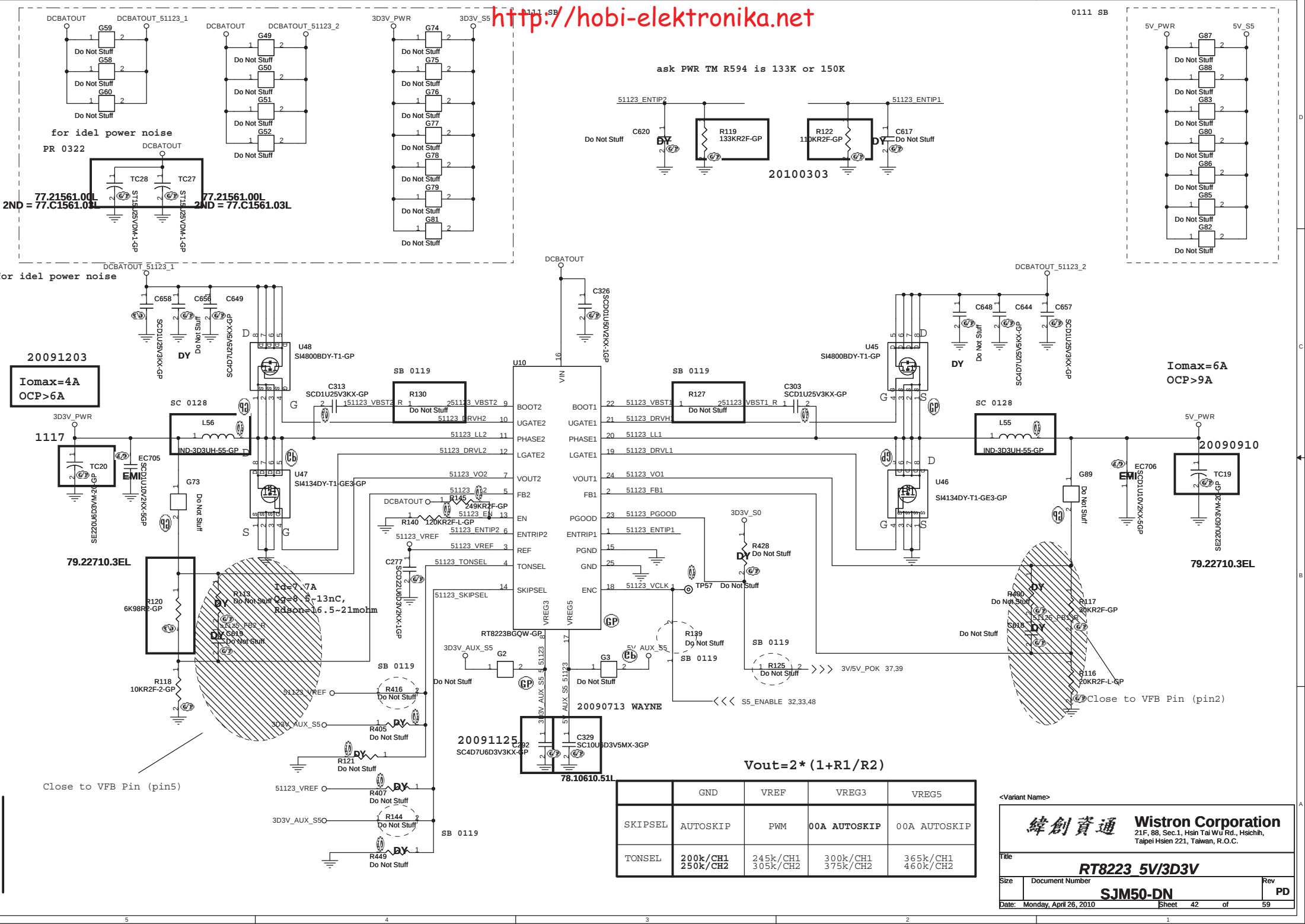


<Core Design>





Title			
CPU Vcore(ISL6265HR)			
Size	Document Number		Rev
Custom	SJM50-DN		P
Date:	Monday, April 26, 2010	Sheet 41 of	59



$V_{out} = 2 * (1 + R1/R2)$

	GND	VREF	VREG3	VREG5
SKIPSEL	AUTOSKIP	PWM	00A AUTOSKIP	00A AUTOSKIP
TONSEL	200k/CH1 250k/CH2	245k/CH1 305k/CH2	300k/CH1 375k/CH2	365k/CH1 460k/CH2

<Variant Name>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title: **RT8223 5V/3D3V**

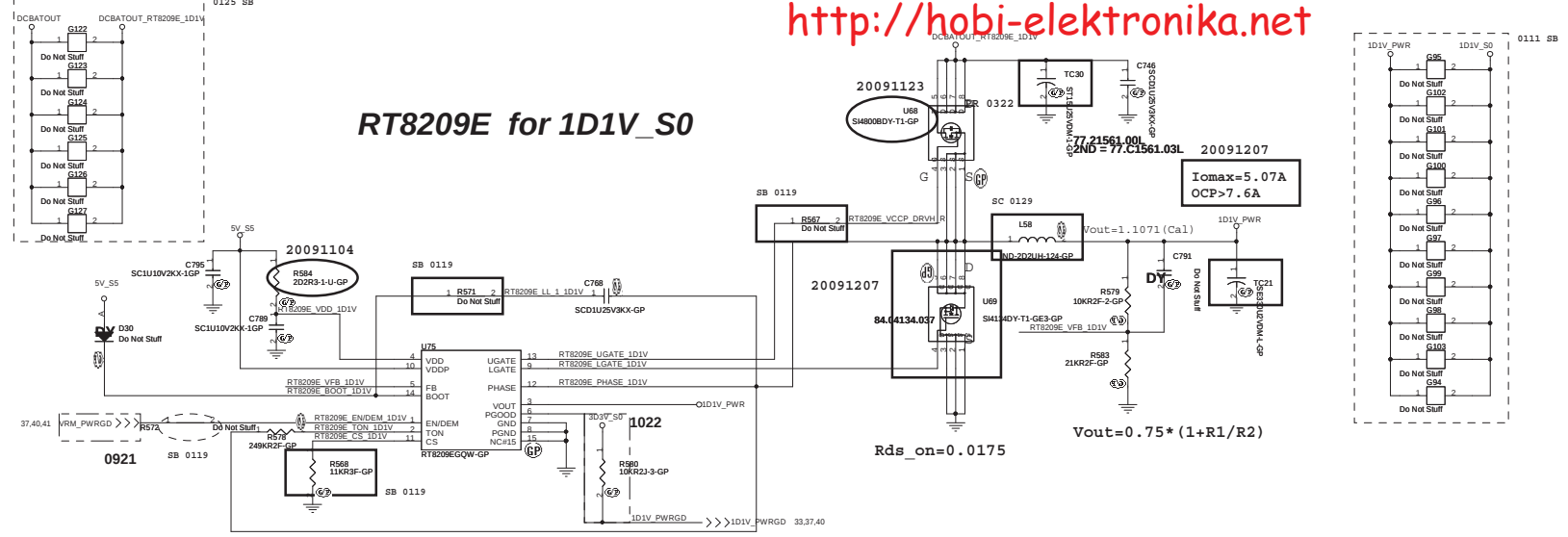
Size	Document Number	Rev
	SJM50-DN	PD
Date: Monday, April 26, 2010	Sheet 42 of 59	



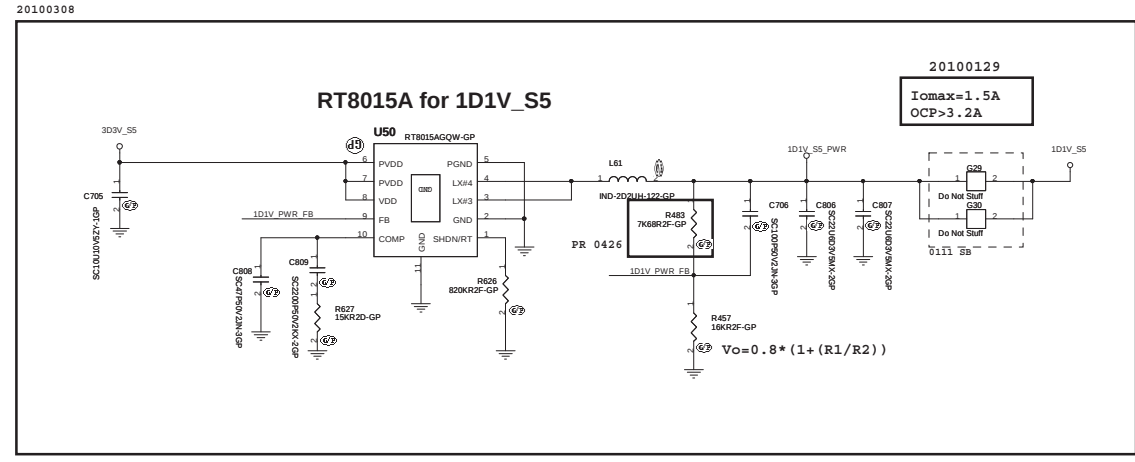
Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

PD

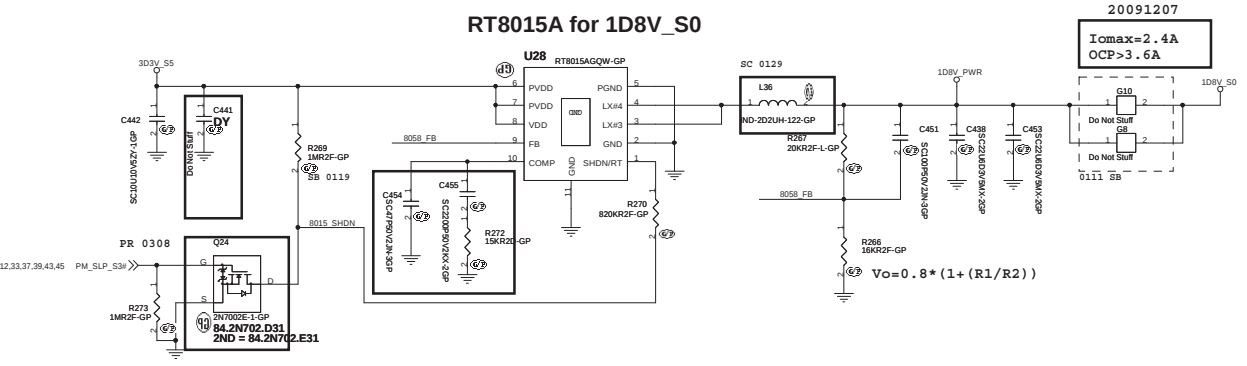
RT209E for 1D1V_S0

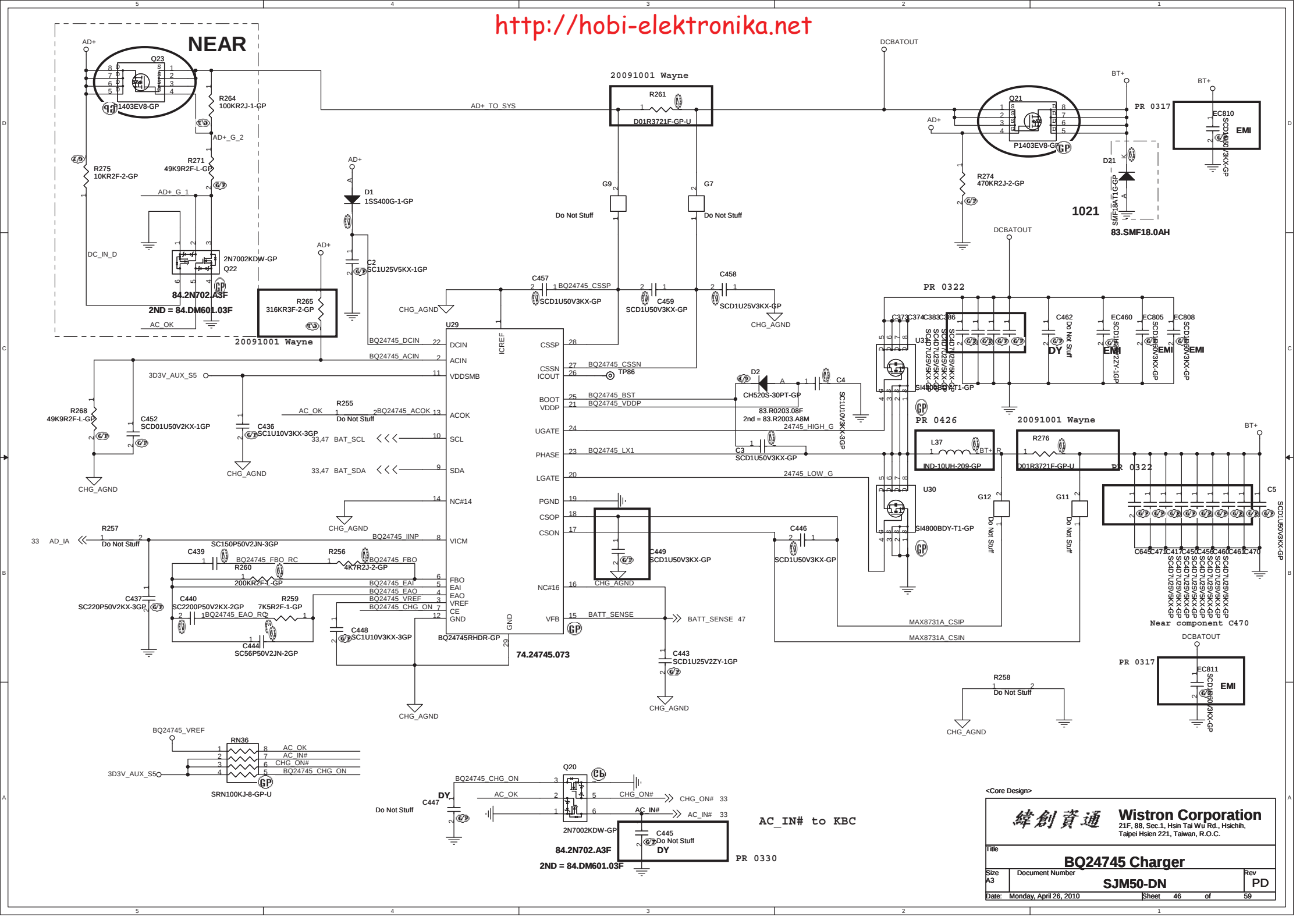


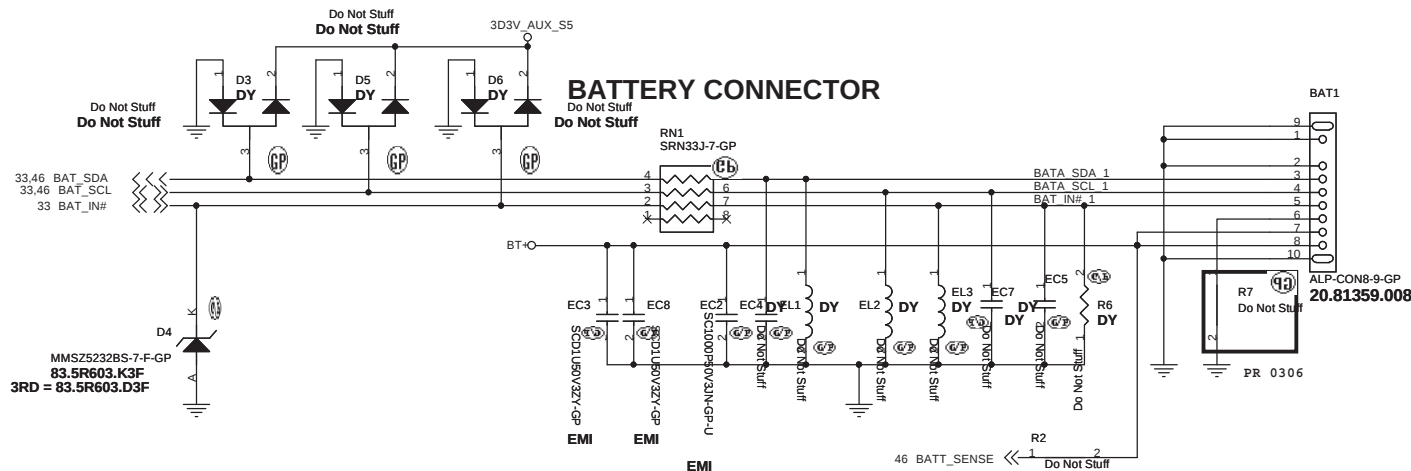
RT8015A for 1D1V_S5

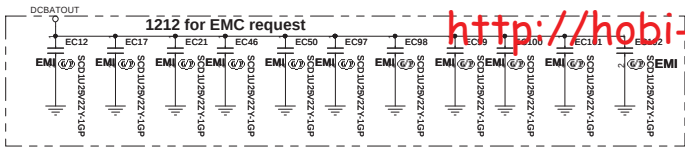
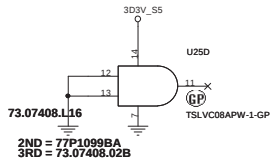


RT8015A for 1D8V_S0

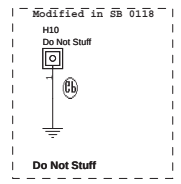
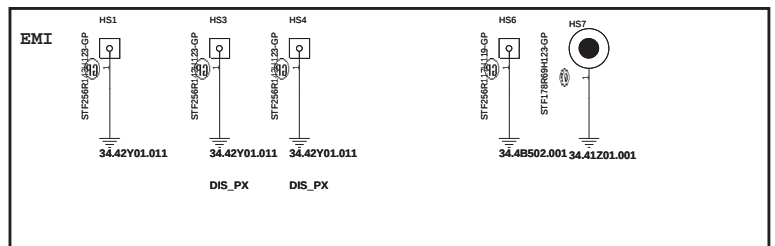
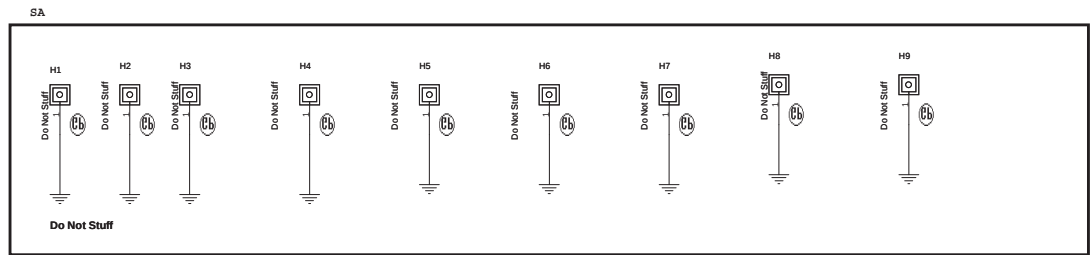
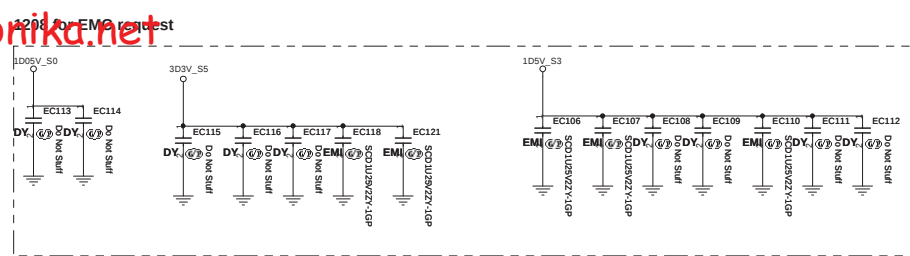




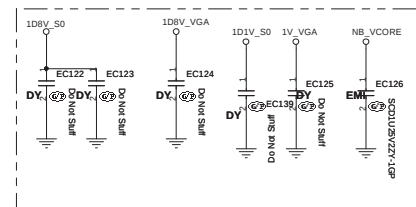




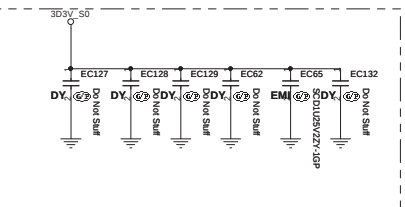
<http://hobi-elektronika.net>



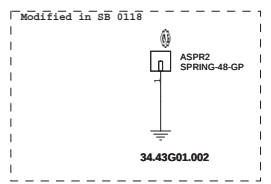
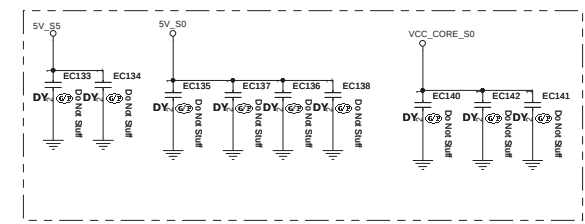
1208 for EMC request



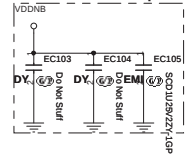
1208 for EMC request



1208 for EMC request



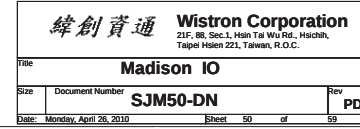
1208 for EMC request



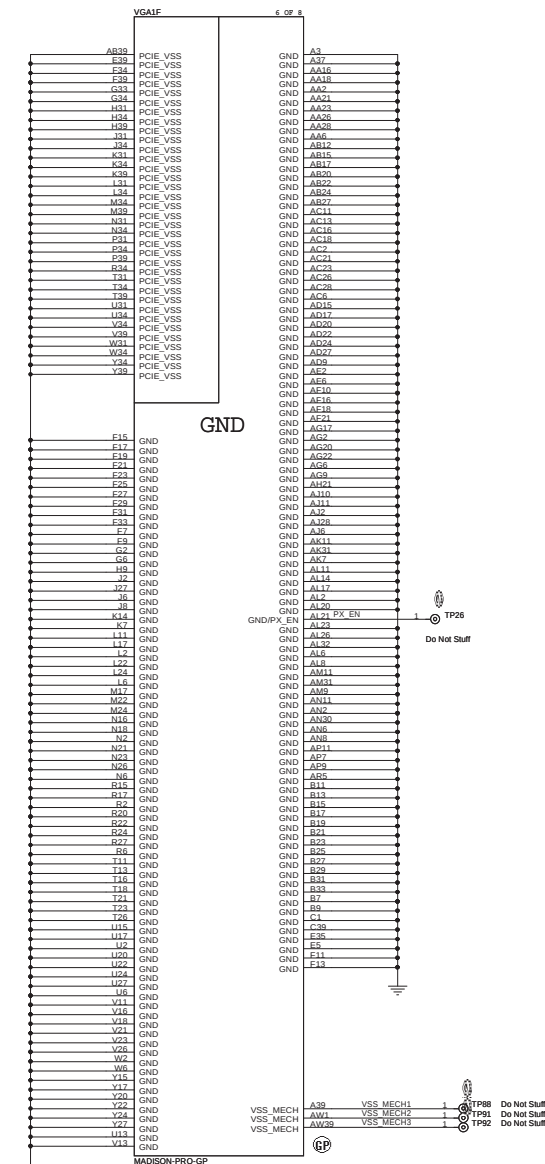
Check test point

3D3V_S0C	1	TP117	Do Not Stuff
3D3V_AUX_S5	1	TP118	Do Not Stuff
3D3V_S5C	1	TP116	Do Not Stuff
5V_S5	1	TP119	Do Not Stuff
12.33 PM_PWRBTN#	<<<	TP121	Do Not Stuff
6.11 CPU_PWRGD	<<<	TP120	Do Not Stuff
32.33.42 S5_ENABLE	<<<	TP115	Do Not Stuff
6.11 CPU_LDT_RST#	<<<	TP122	Do Not Stuff

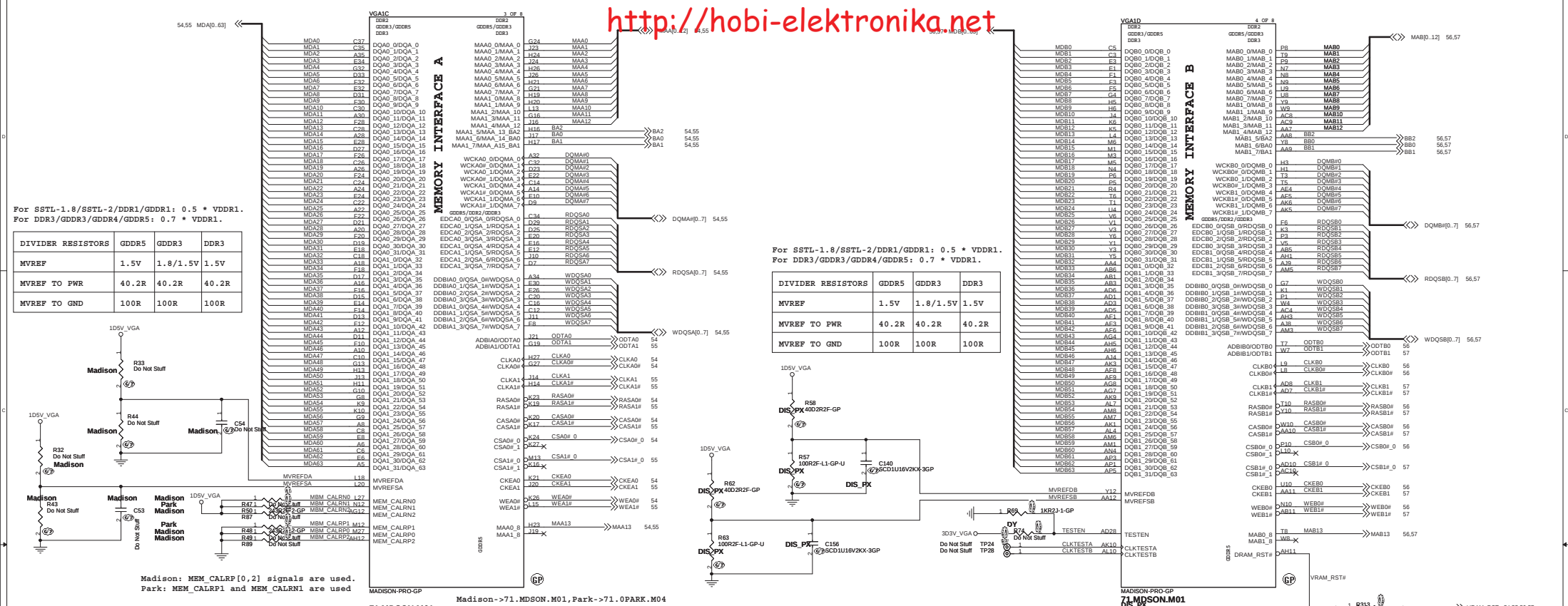
Test Point放在Dimm Door打開可量測處







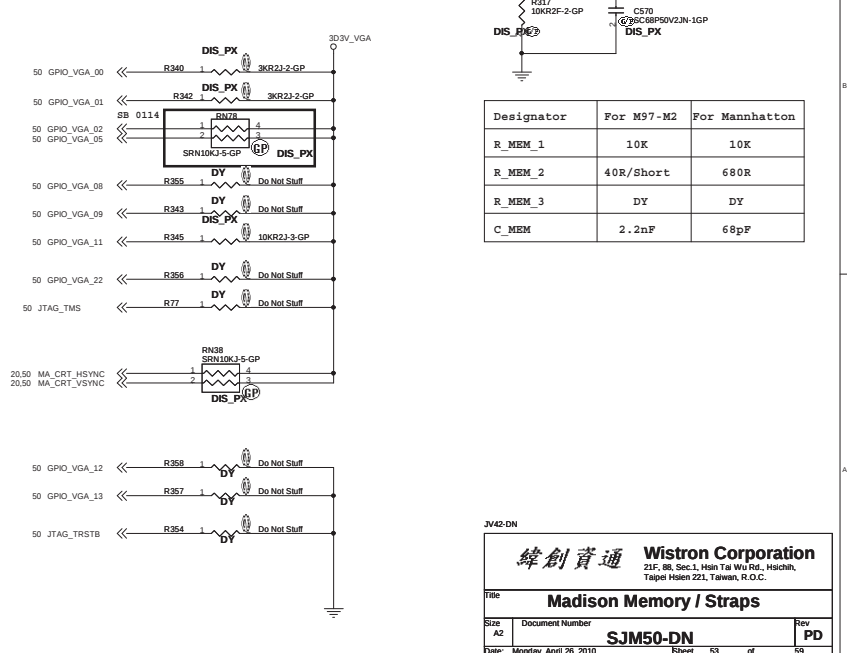
DIS_PX

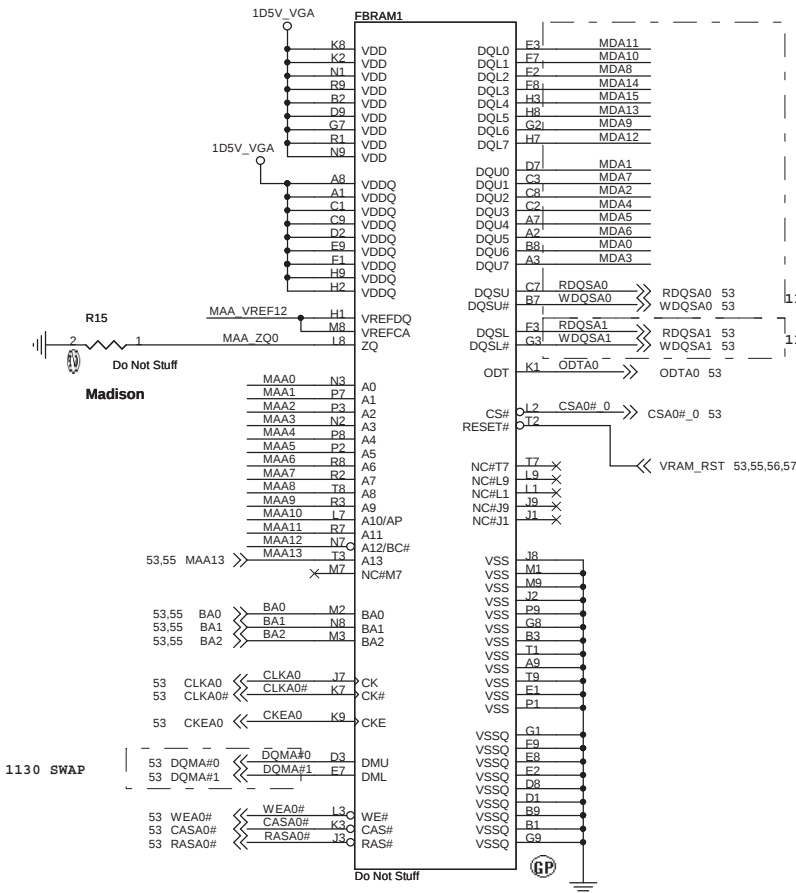


DIS_PX			
STRAPS	PIN	DESCRIPTION	RECOMMENDED SETTINGS 0= DO NOT INSTALL RESISTOR 1= INSTALL 10K RESISTOR x = DESIGN DEPENDANT NA = NOT APPLICABLE
TX_PWRS_ENB (Internal PD)	GPIO0	PCI FULL TX OUTPUT SWING Transmitter Power Savings Enable 0= 50% Tx output swing 1= Full Tx output swing	x
TX_DEEMPH_EN (Internal PD)	GPIO1	Transmitter De-emphasis Enable 0= Tx de-emphasis disabled 1= Tx de-emphasis enabled	x
RESERVED	GPIO8	RESERVED	0
BIF_VGA_DIS	GPIO9	VGA ENABLED	0
RESERVED	GPIO21	RESERVED	0
BIOS_ROM_EN	GPIO22_ROMCSB	ENABLE EXTERNAL BIOS ROM	0
VIP_DEVICE_STRAP_ENA (Internal PD)	GPIO[13,12,11]	SERIAL ROM TYPE OR MEMORY APERTURE SIZE SELECT if BIOS_ROM_EN=1, then Config[3:0] defines the ROM type if BIOS_ROM_EN=0, then Config[3:0] defines the primary memory aperture size	x x x
RSVD	V2SYNC		0
RSVD	H2SYNC		0
AUD[1] AUD[0] (Internal PD)	VGA_HSYNC VGA_VSYNC	AUD[1:0] 00: No audio function 01: Audio for DisplayPort and HDMI (if adapter is detected) 10: Audio for DisplayPort only 11: Audio for both DisplayPort and HDMI	x x

AMD RESERVED CONFIGURATION STRAPS ALLOW FOR PULLUP PADS FOR THESE STRAPS AND IF THESE GPIOs ARE USED, THEY MUST NOT CONFLICT DURING RESET H2SYNC, GENERIC_C, GPIO2, GPIO21
--

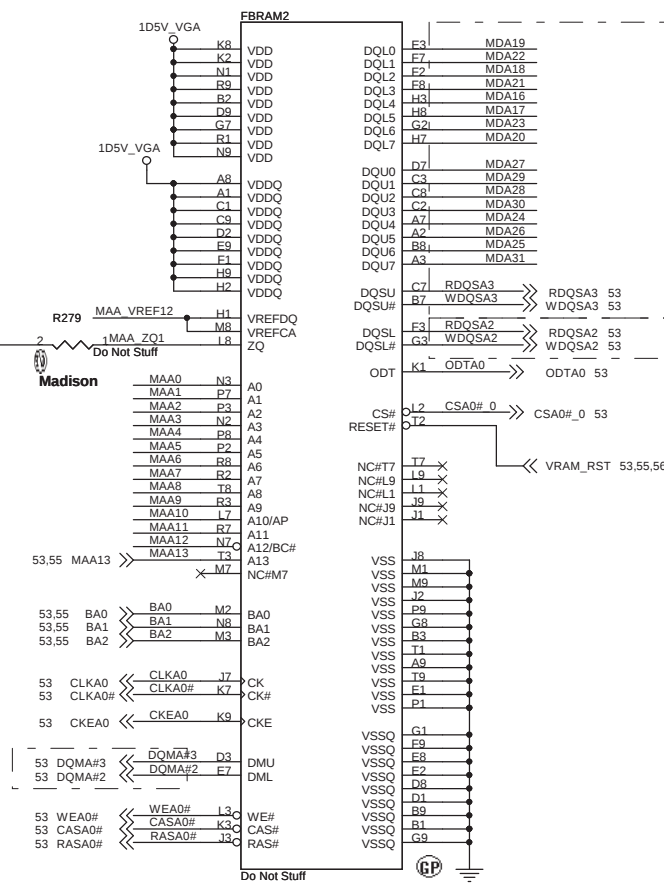
If BIOS_ROM_EN (GPIO22) = 0			If BIOS_ROM_EN (GPIO22) = 1		
Size of the primary memory apertures		GPIO[13,12,11]	Manufacturer	Part Number	GPIO[13,12,11]
V	128MB	x000	ST Microelectronics	M25P05A	0100
	256MB	x001		M25P10A	0101
	64MB	x010		M25P20	0101
	32MB	x		M25P40	0101
	512MB	x		M25P80	0101
	1GB	x	Chingia (formerly PMC)	Pm25LV512A	0100
	2GB	x		Pm25LV010A	0101
4GB	x				



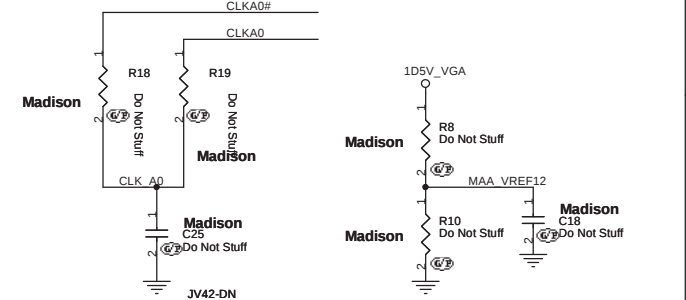
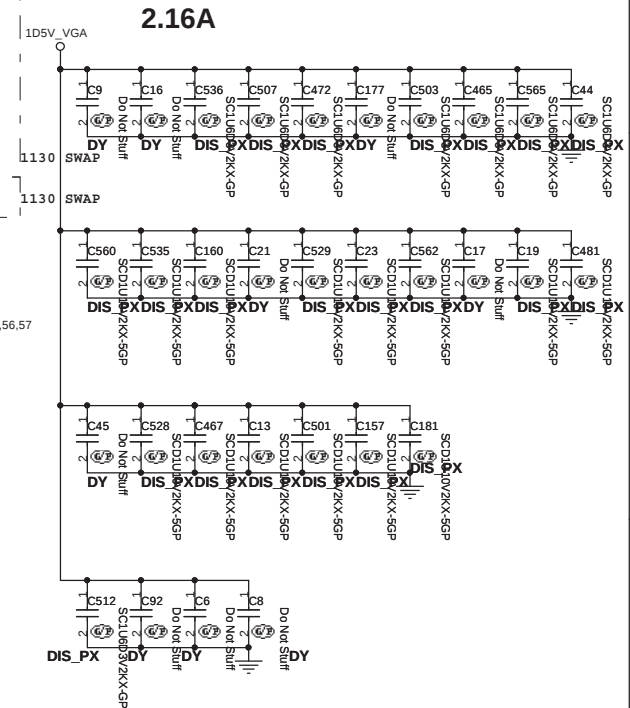


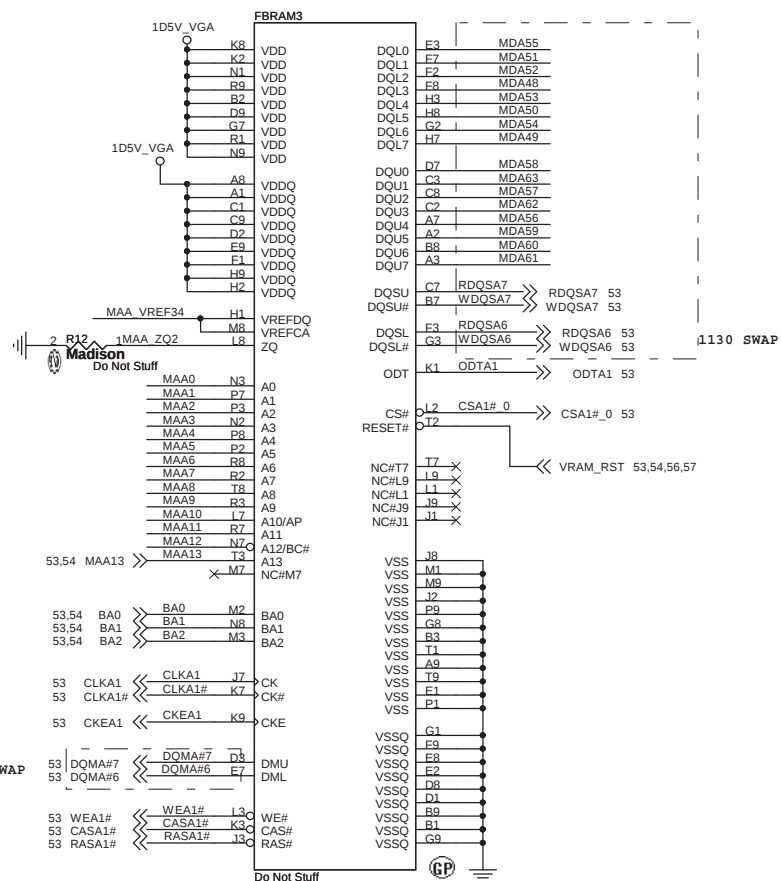
Do Not Stuff
Madison

SAMSUNG: 72.41164.H0U
HYNIX: 72.51G63.C0U



Do Not Stuff
Madison

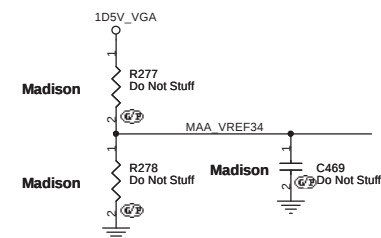
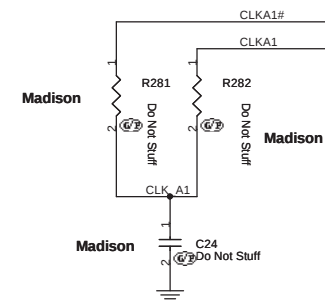
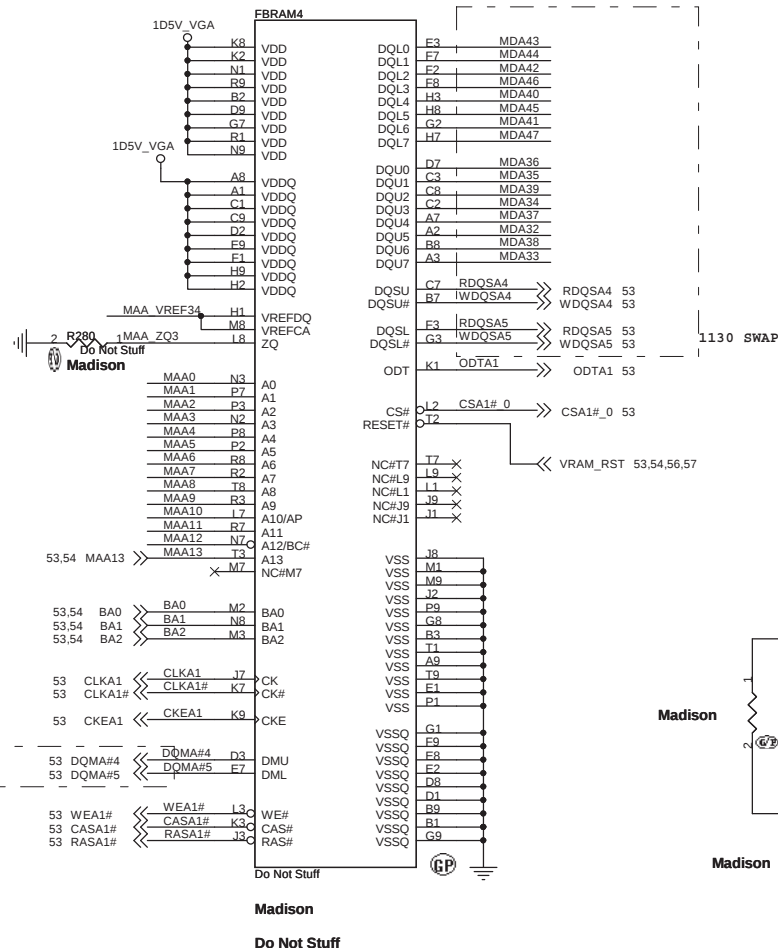




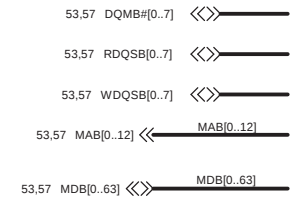
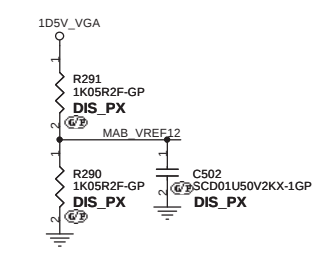
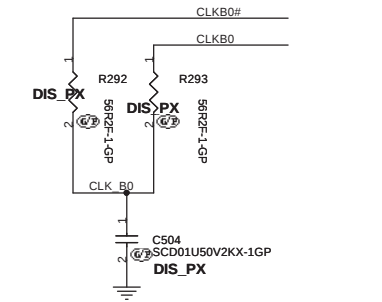
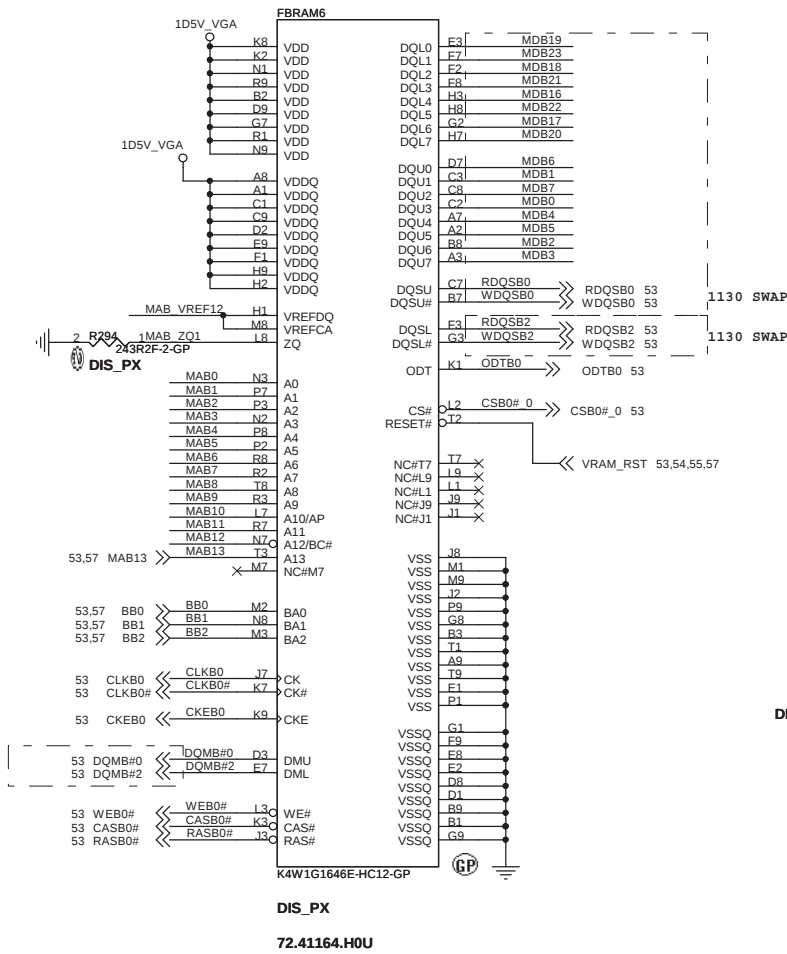
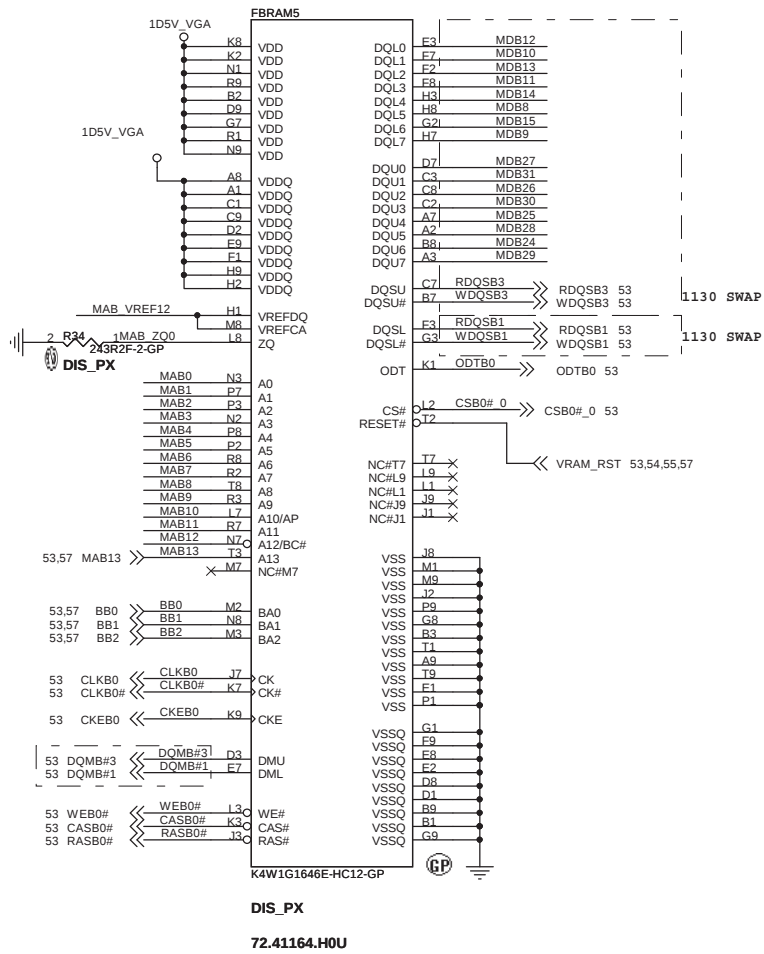
Do Not Stuff

Madison

```
SAMSUNG: 72.41164.H0U
HYNIX:   72.51G63.C0U
```



http://hobi-elektronika.net
DDR3



SAMSUNG: 72.41164.H0U
HYNIX: 72.51G63.C0U



72.41164.H0U

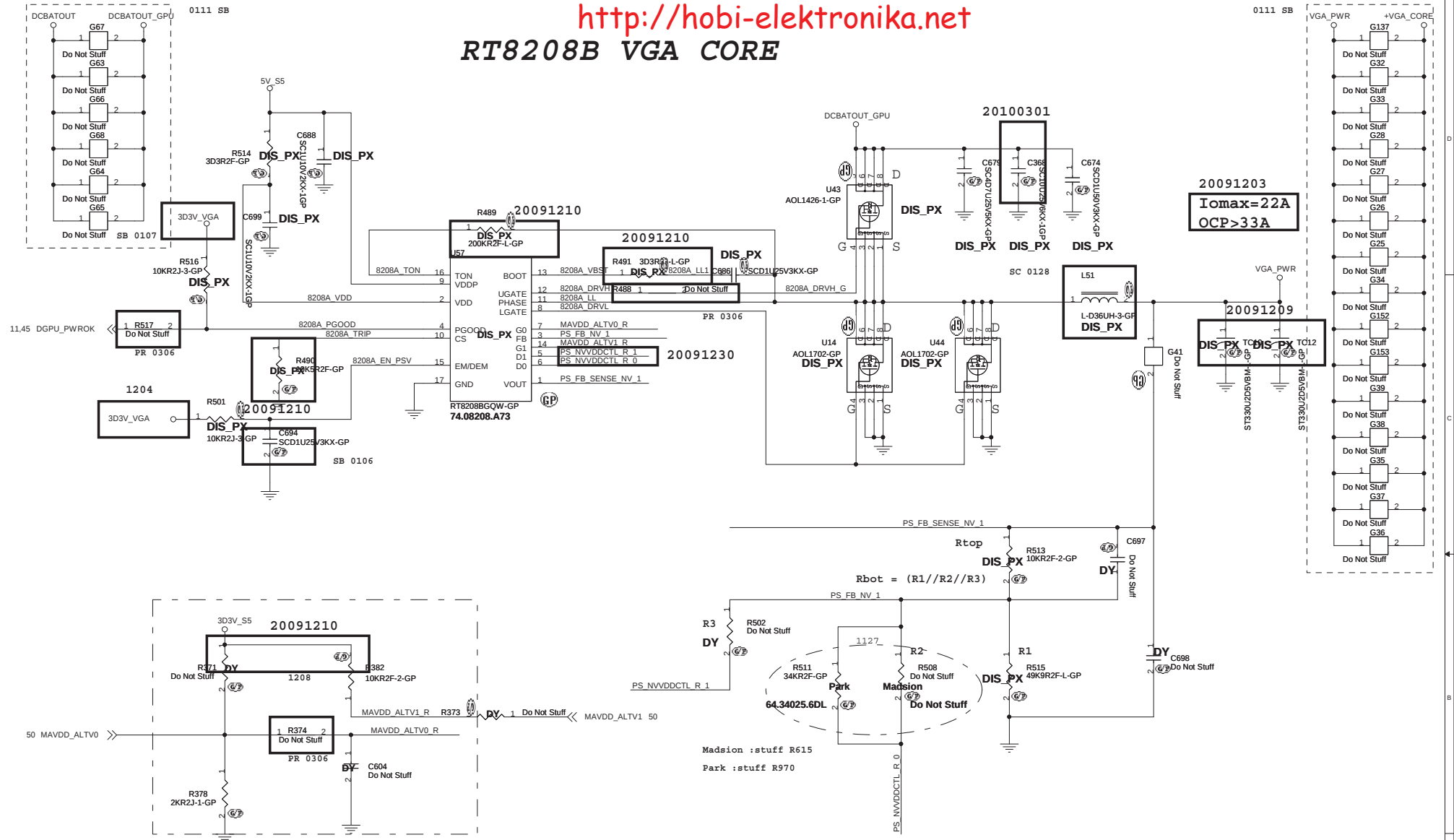
```
HYNIX:      72.51G63.C0U
```



72.41164.H0U



<http://hobi-elektronika.net>
RT8208B VGA CORE



MADSION PRO

	I/O	Inter Pull Low	GPIO TABLE
NVVDD_ALTV0	O	YES	GPU VOLTAGE L: 1.00V GPU VOLTAGE H: 0.90V

PARK XT

	I/O	Inter Pull Low	GPIO TABLE
NVVDD_ALTV0	O	YES	GPU VOLTAGE L: 1.12V GPU VOLTAGE H: 0.90V

Discrete Park Samsung

緯創資通 Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichin, Taipei Hsien 221, Taiwan, R.O.C.	
Title RT8208E VGA CORE	
Size Custom	Document Number SJM50-DN
Date: Monday, April 26, 2010	Sheet 58 of 59

BOM

NB
RS780-->RS880M
71.RS780.M02-->71.RS880.M02

SB
SB820M-1-GP
71.SB820.00U-->71.SB820.M03

SATA_CALRP
A11: 80 歐姆 1% resistor to GND
A12: TBD 歐姆 1% resistor to GND

SATA_CALRN
A11:A11: 931 歐姆 1% resistor to VDDAN_11_SATA
A12: TBD 歐姆 1% resistor to VDDAN_11_SATA.

VGA
Madison--> PN:71.MDSON.M01
Park--> PN:71.0PARK.M04

VRAM
Samsung-->VRAM FBRAM1~8 PN:VR.1GB0B.006
Hynix--> VRAM FBRAM1~8 PN:VR.1GB0G.004
ATI-> VRAM FBRAM1~8 PN:VR.1GB0T.002

HDMI
R217 : DIS & PX-->100K
UMA-->10K(63.10334.1DL R402H16 10KR2J-3-GP)

R341 : DIS & PX-->0 OHM
UMA-->5.1K(63.51234.1D1 5.1K J 1/16W 0402)

Side port
Samsung-->VRAM FBRAM1~8 PN:VR.1GB0B.006
Hynix--> VRAM FBRAM1~8 PN:VR.1GB0G.004
ATI-> VRAM FBRAM1~8 PN:VR.1GB0T.002

CRT
UMA-->L1-->2R 0603
C30-->47U/6.3V
DIS-->L1-->Bead(L1 68.00217.711 L1608-UH38 SBK160808T-221Y-N-GP)
C30-->DY
PX--> 150 歐姆 (R521 64.15005.6DL CHIP RES 150 F 1/16W 0402)

MINI1
MINI1--> 20.F1516.052

1st -> PX Diserete Madison Samsung
Side port -> Samsung
HDMI ->NO repeater

1nd -> PX Diserete Park Hynix
Side port -> Hynix
HDMI ->repeater

1st -> UMA
Side port -> Samsung
HDMI ->NO repeater

<Variant Name>		
緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title		
NOTE		
Size	Document Number	Rev
A3	SJM50-DN	PD
Date:	Monday, April 26, 2010	Sheet 59 of 59